



# PERFORMANCE TEST REPORT

## HORUS420-R1

S/N: SR2025100901

| Product Manager | Mechanical Engineer | System Engineer | Test Engineer |
|-----------------|---------------------|-----------------|---------------|
| Honwen Huang    | Jeff Lin            | Orpheus Hsiung  | Mike Chen     |

Date: January 27, 2026

# PERFORMANCE TEST REPORT

## HORUS420-R1

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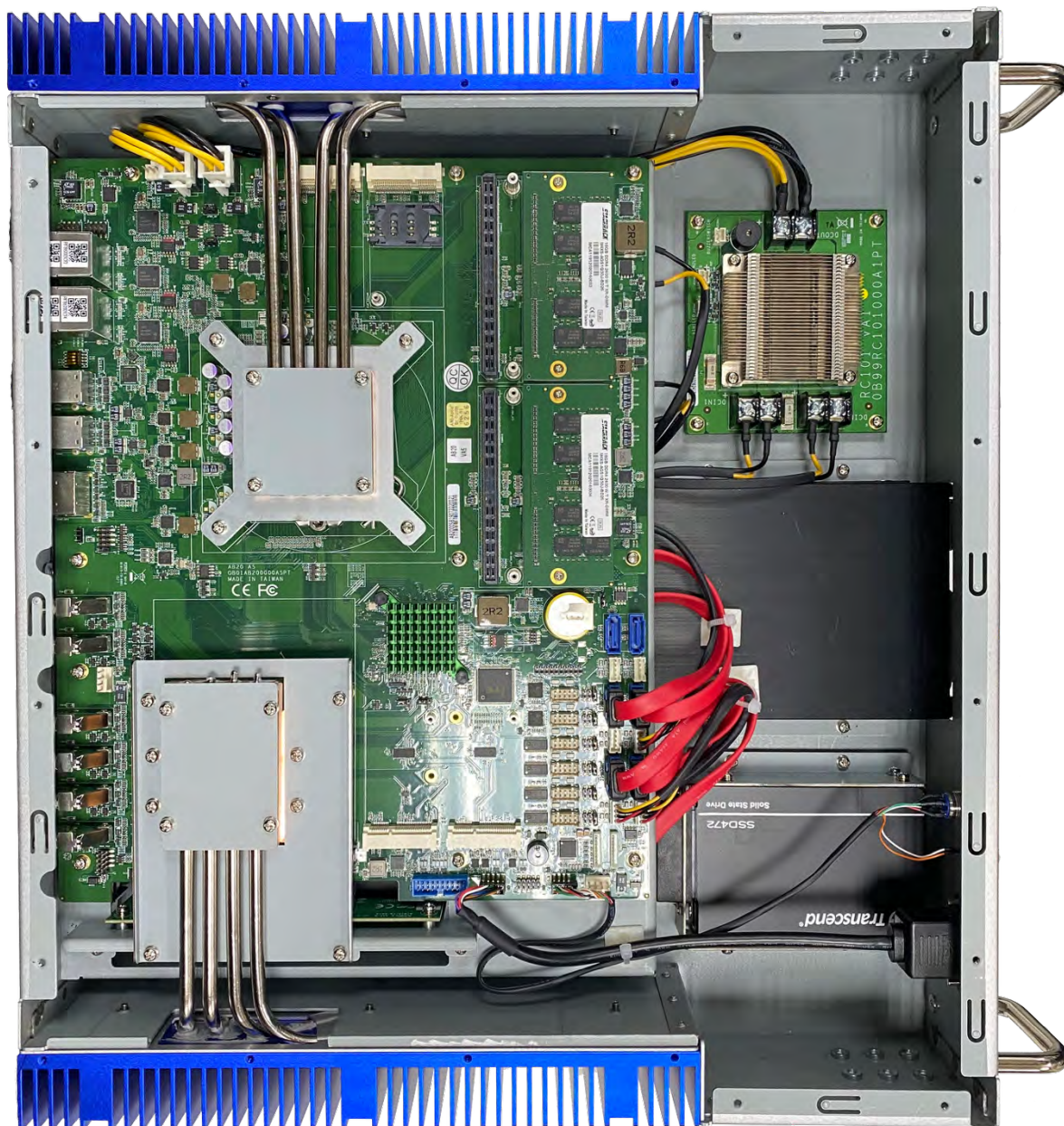
# 1. SPECIFICATION

## 1-1. SYSTEM CONFIGURATION

|                     |   |
|---------------------|---|
| <b>Motherboard</b>  | AB20<br>BIOS Version: 5.11<br>SMBIOS Version: 3.0<br>Supports Intel® LGA 1151 14nm Skylake-S Processor<br>Operating Temp. -40°C~85°C  |
| <b>CPU</b>          | Intel® Core™ i7-6700TE Processor<br>Total Cores: 14<br>Total Cores: 4<br>Total Threads: 8<br>Max Turbo Frequency: 3.40 GHz<br>Intel® Turbo Boost Technology 2.0 Frequency†: 3.40 GHz<br>Processor Base Frequency: 2.40 GHz<br>TDP: 35 W |
| <b>Memory</b>       | 32GB DDR4 XR-DIMM   |
| <b>Storage</b>      | Internal: 2TB *2 3D TLC SSD<br>External: 2TB *2 3D TLC SSD  |
| <b>GPU</b>          | NVIDIA GeForce GTX 1050 Ti Embedded GPU<br>BIOS Version: 86.07.59.00.E3<br>CUDA parallel-processing cores: 768 CUDA® cores<br>GPU base/boost clock: 1291 MHz / 1392 MHz<br>Max Power Consumption: 75 W                                  |
| <b>Add-on cards</b> | Perfectron MT201 Intel® 82599ES 10Gb/s 2 x LAN port<br>2 x SFP+ LAN ports<br>Supports 10Gb/s per port<br>Intel® 82599ES<br>PCIe x8 (Gen2 x8 bus)  |
| <b>Power Module</b> | 2 x 200W AC-DC PSU With redundant Power   |



## 1-2. PRODUCT INTERIOR PHOTO



## 2. TEST PLAN

### 2-1. THERMAL MEASUREMENT PROCESS

|                               |  |
|-------------------------------|--|
| <b>Test Purpose</b>           | <p>The purpose of conducting thermal profile testing is to identify potential thermal issues in the Equipment Under Test (EUT). Given that semiconductor failure rates increase significantly with rising junction temperatures, this testing contributes to the overall assessment of product reliability.</p> <p>As the system undergoes a cooling phase, operational modes may shift depending on stack configuration, temperature, and heat dissipation characteristics. Thermal mapping provides critical insight for optimizing thermal management strategies and determining the most effective component layout and monitoring arrangements.</p>   |
| <b>Test Equipment</b>         | 1. KSON THS-B4T-150 Chamber.   |
| <b>Quantity Tested</b>        | Minimum 1 Set  |
| <b>Test Software</b>          | CPU Stress: PassMark BurnIn Test v9.0<br>GPU Stress: AIDA64 Business v6.90<br>LAN Speed Test: iPerf3   |
| <b>Test Procedure</b>         | <p>1. Thermal Pre-Scan Measurement:<br/>           Temperature Range: <b>-40°C to 60°C</b><br/>           Humidity Condition: <b>60% RH</b> (when temperature exceeds 25°C)</p> <p>2. Actual Thermal Measurement Procedure:</p> <ol style="list-style-type: none"> <li>2.1. Identify the test points using the infrared thermal image and attach thermocouples to the identified hot spots.</li> <li>2.2. Place the Equipment Under Test (EUT) in the thermal chamber and configure the test temperature profile according to the specified requirements.</li> <li>2.3. Power on the EUT after closing the thermal chamber. Boot into Windows 10 Pro and initiate a maximum power consumption and stress test.</li> <li>2.4. After running the test software continuously for 8 hours, record the peak temperature observed at each thermocouple measurement point.</li> <li>2.5. Power off both the thermal chamber and the EUT.</li> <li>2.6. Verify that the recorded temperature data for each component remains within its specified operating temperature range, as defined in the component specification or approval documents.</li> </ol> |
| <b>Test Diagram of Curves</b> | <p>Environment defines for 174 hours.</p>  |

## 2-2. TEST RESULT

### 2-2-1. Temperature Cycle

# Aging tests were performed on individual components across a range of temperature settings, under both maximum load and full load conditions, to evaluate thermal endurance and operational stability over time.

| Test Temperature    | Test Result |
|---------------------|-------------|
| <b>-40°C / 0%RH</b> | <b>PASS</b> |
| <b>-20°C / 0%RH</b> | <b>PASS</b> |
| <b>0°C / 0%RH</b>   | <b>PASS</b> |
| <b>25°C / 60%RH</b> | <b>PASS</b> |
| <b>40°C / 60%RH</b> | <b>PASS</b> |
| <b>50°C / 60%RH</b> | <b>PASS</b> |
| <b>60°C / 60%RH</b> | <b>PASS</b> |

### 2-2-2. I/O Function

# Confirm that the system specifications and all input/output (I/O) interfaces are correctly configured and functioning as intended, in accordance with the defined technical standards.

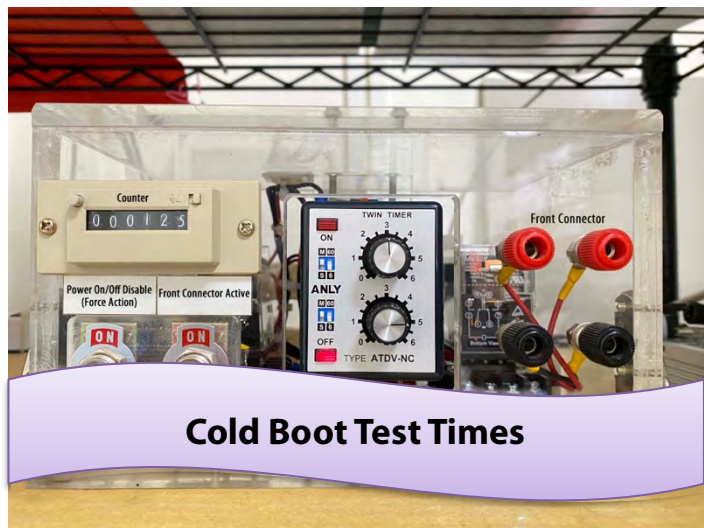
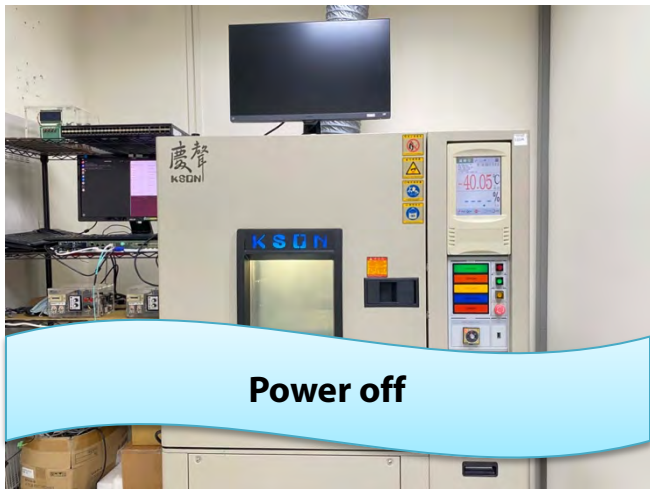
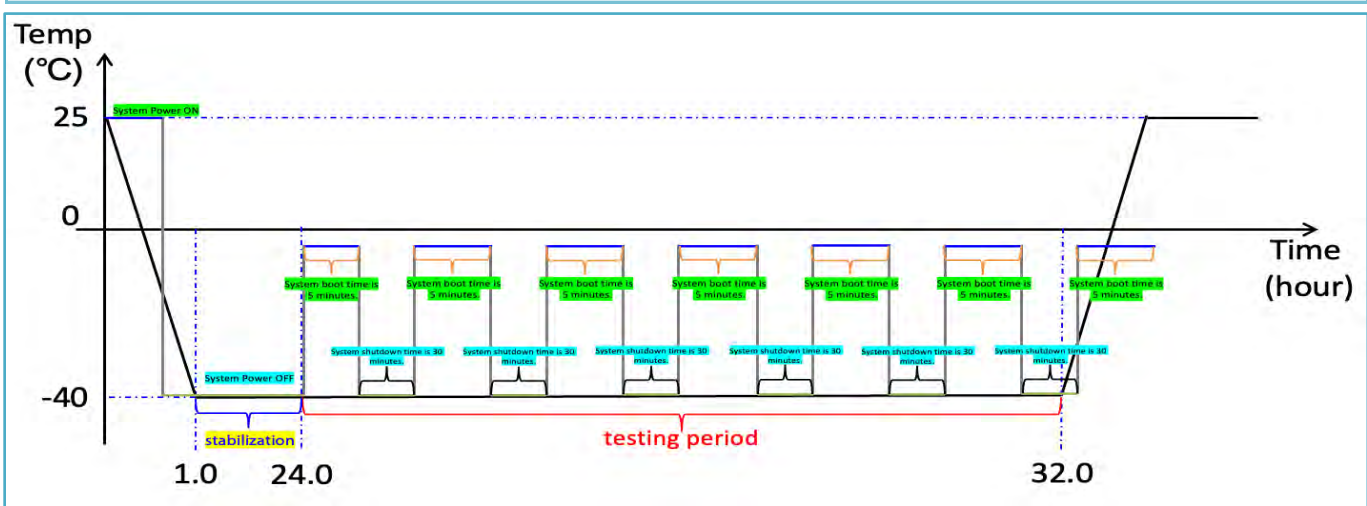
| Item                | Test Criteria  | Result      |
|---------------------|--|-------------|
| <b>USB 2.0</b>      | A PassMark USB_2.0 Loopback was connected for testing and was found to be functioning normally.  | <b>PASS</b> |
| <b>USB 3.0</b>      | A PassMark USB_3.0 Loopback was connected for testing and was found to be functioning normally.  | <b>PASS</b> |
| <b>Display Port</b> | The DP output has been verified to be working properly, and the resolution can be adjusted according to the monitor size.  | <b>PASS</b> |
| <b>1GbE LAN</b>     | Data transmission via connection to a 1 Gbps LAN switch has been tested. The transfer speed meets the required standard with zero packet loss, confirming normal functionality.  | <b>PASS</b> |
| <b>10GbE LAN</b>    | Data transmission via connection to a 10 Gbps LAN switch has been tested. The transfer speed meets the required standard with zero packet loss, confirming normal functionality. | <b>PASS</b> |



### 2-2-3. Low Temperature Power Cycle Test

# Apply power to the system under a -40°C ambient condition and confirm successful system boot-up, ensuring stable initialization and operation at low temperatures.

| Ambient Temp. | Cold Boot Test Times | Test Result |
|---------------|----------------------|-------------|
| -40°C         | 125 times            | PASS        |

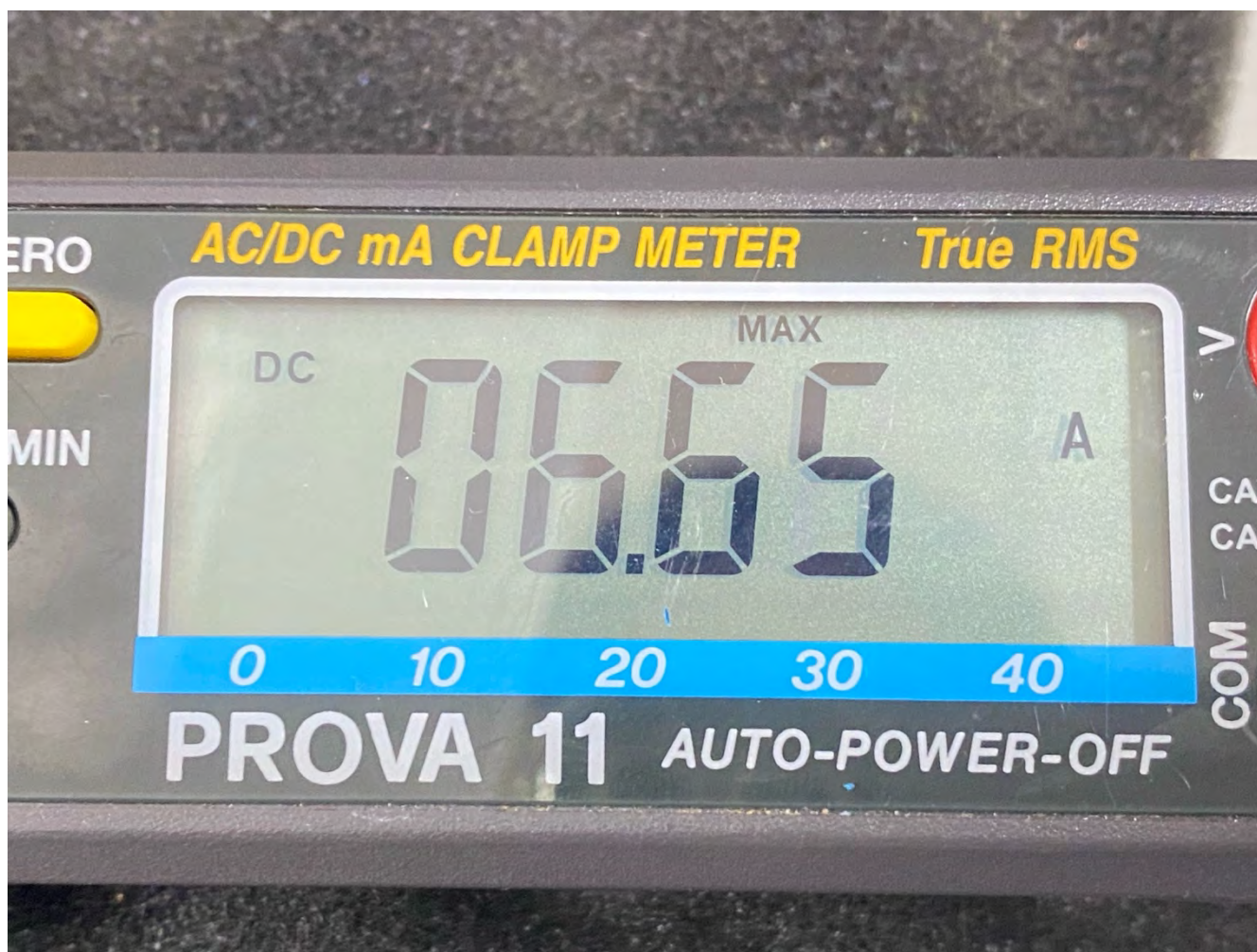


## 2-3. PEAK INSTANTANEOUS CURRENT AND POWER

Maximum instantaneous current and power measured during the entire period from system power-on to operating system initialization.

The current value was measured at the output terminal of the internal DC-DC redundant board.

| Voltage (V) | Peak Instantaneous Current (A) | Peak Instantaneous Power (W) |
|-------------|--------------------------------|------------------------------|
| 12.0        | 6.65                           | 79.8                         |

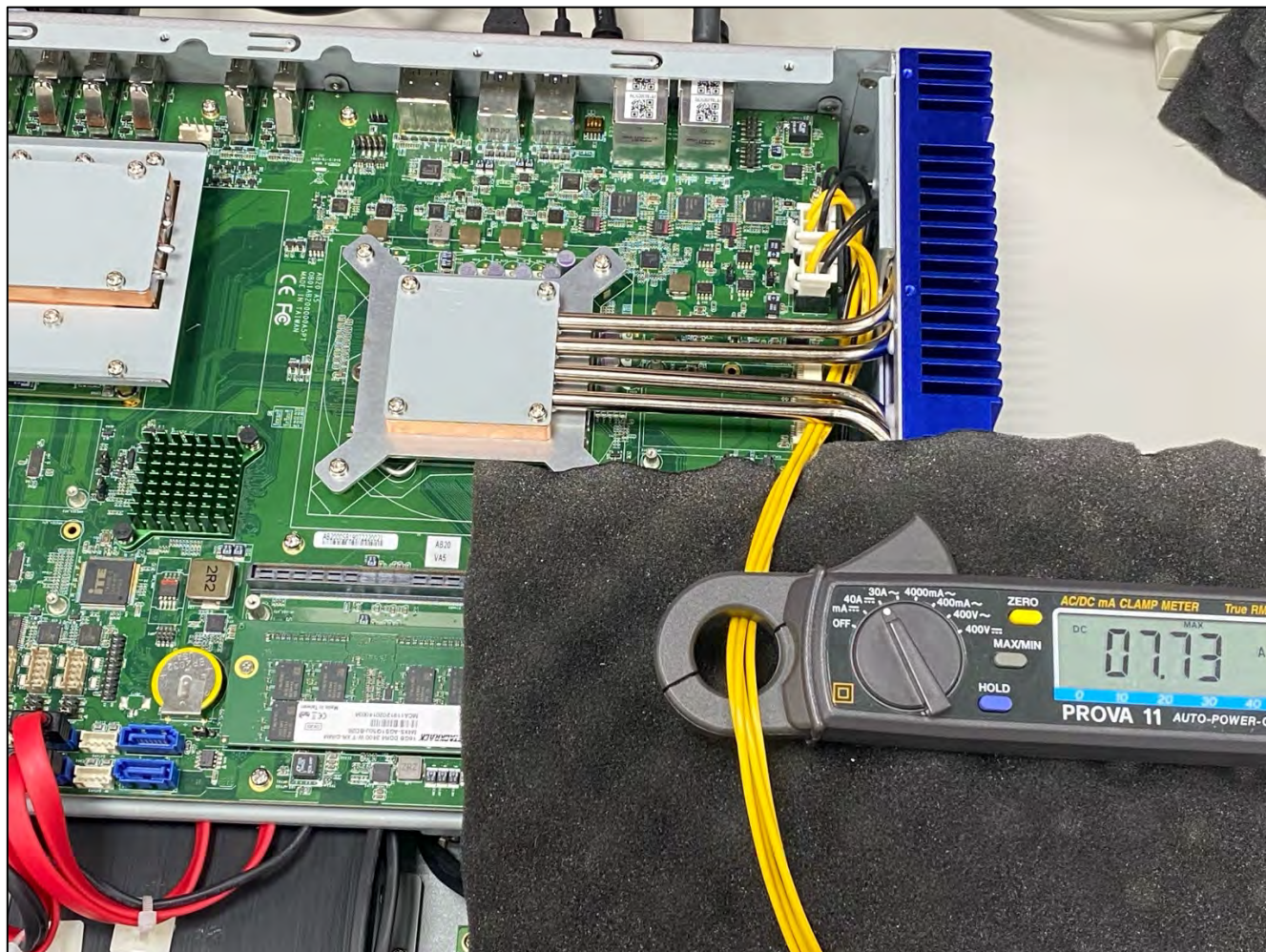




## 2-4. POWER CONSUMPTION

**The current value was measured at the output terminal of the internal DC-DC redundant board.**

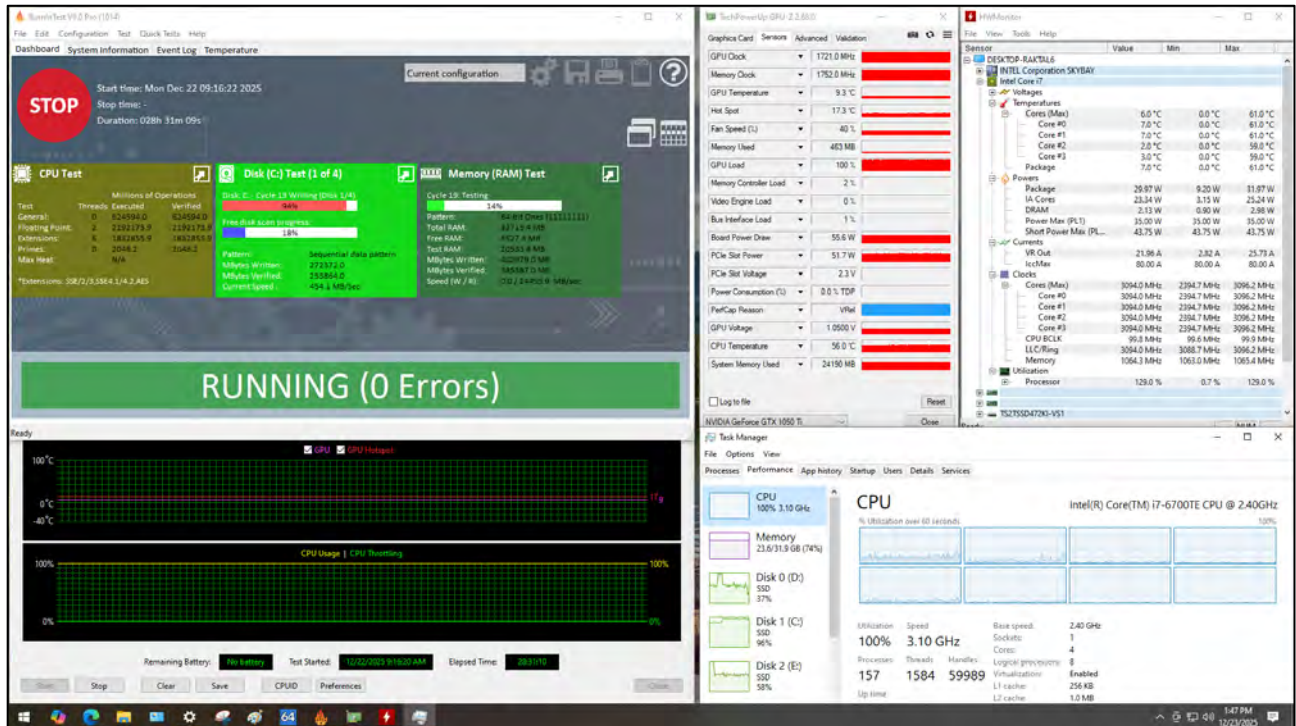
| Voltage (V) | Current (A) | Wattage (W) |
|-------------|-------------|-------------|
| 12.0        | 7.73        | 92.76       |





### 3. TEST PHOTO IN LAB

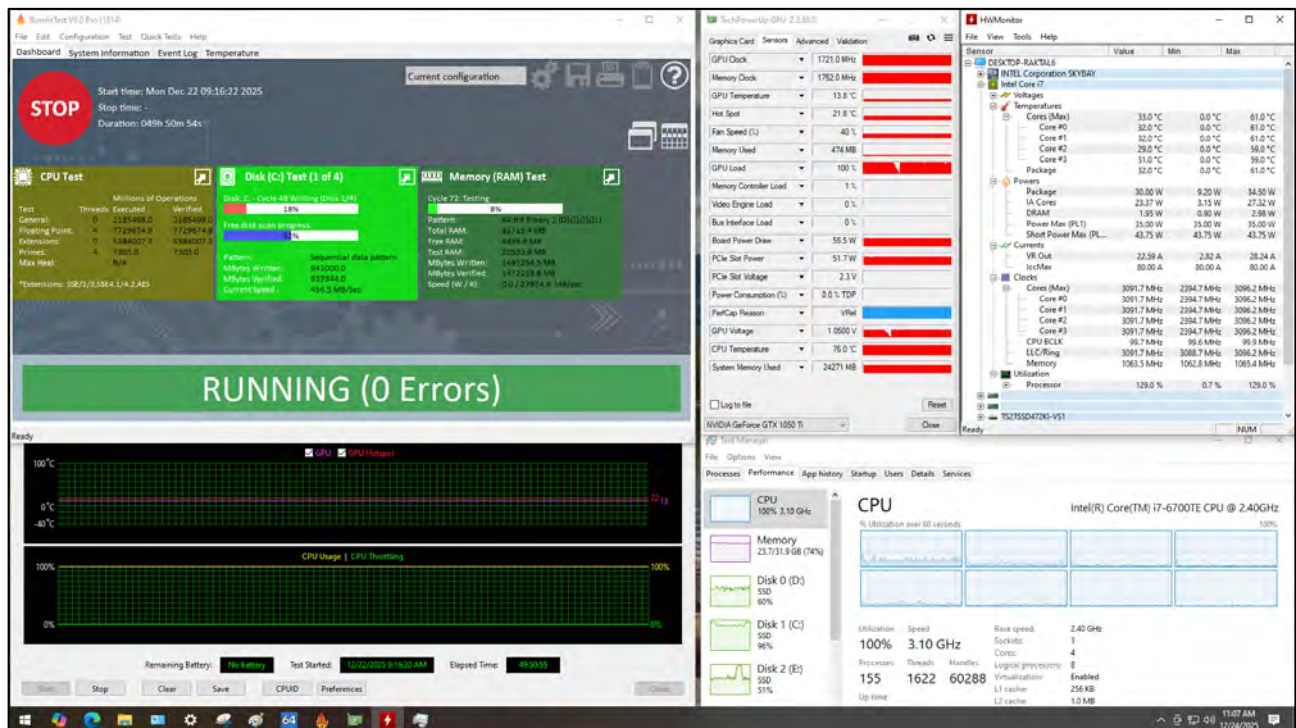
- Chamber in -40°C / 0%RH



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- Chamber in -20°C / 0%RH

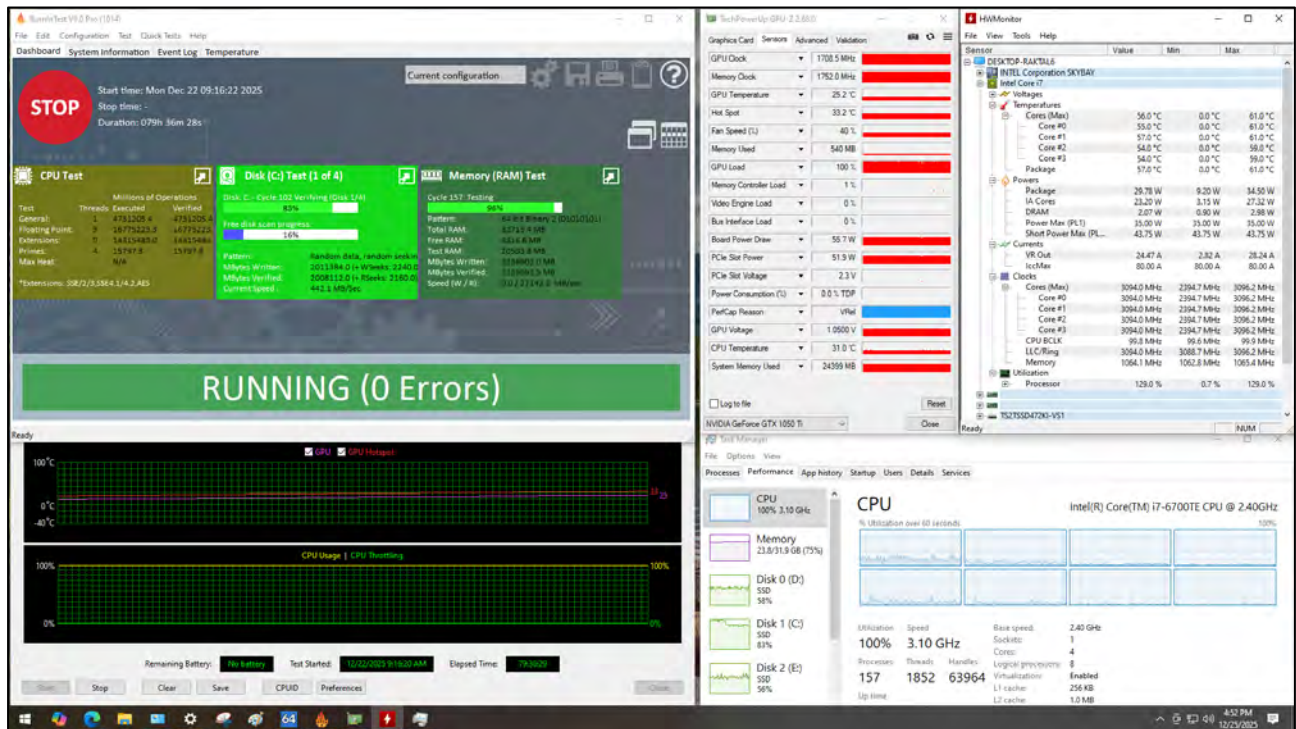




# PERFORMANCE TEST REPORT

## HORUS420-R1

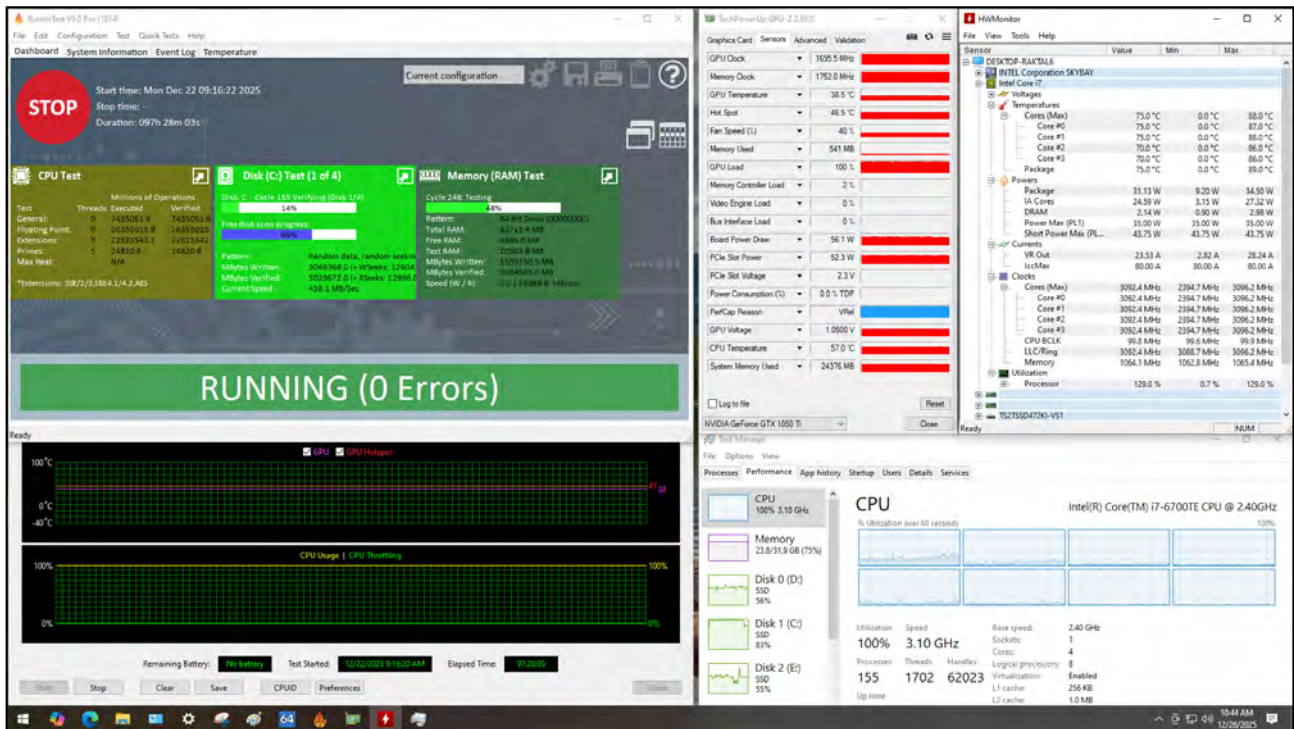
- Chamber in 0°C / 0%RH



# PERFORMANCE TEST REPORT

## HORUS420-R1

### - Chamber in 25°C / 60%RH

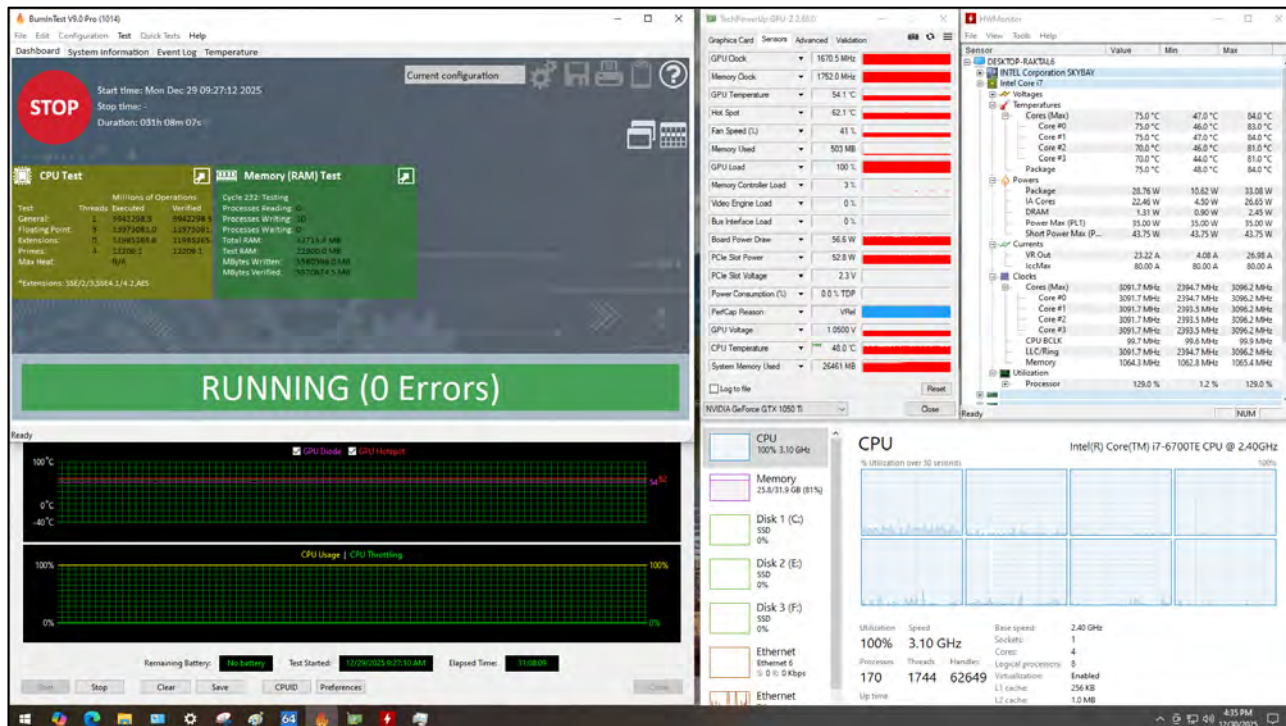




# PERFORMANCE TEST REPORT

## HORUS420-R1

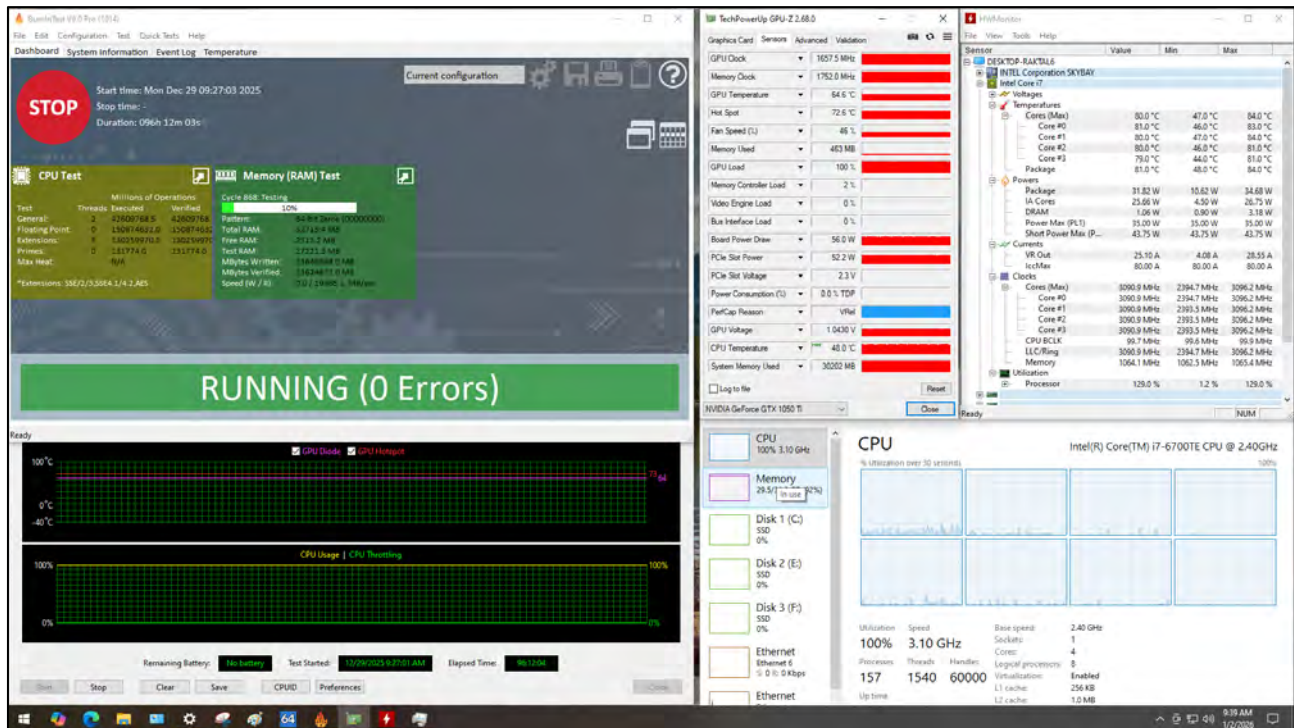
### - Chamber in 40°C / 60%RH



# PERFORMANCE TEST REPORT

## HORUS420-R1

- Chamber in 50°C / 60%RH

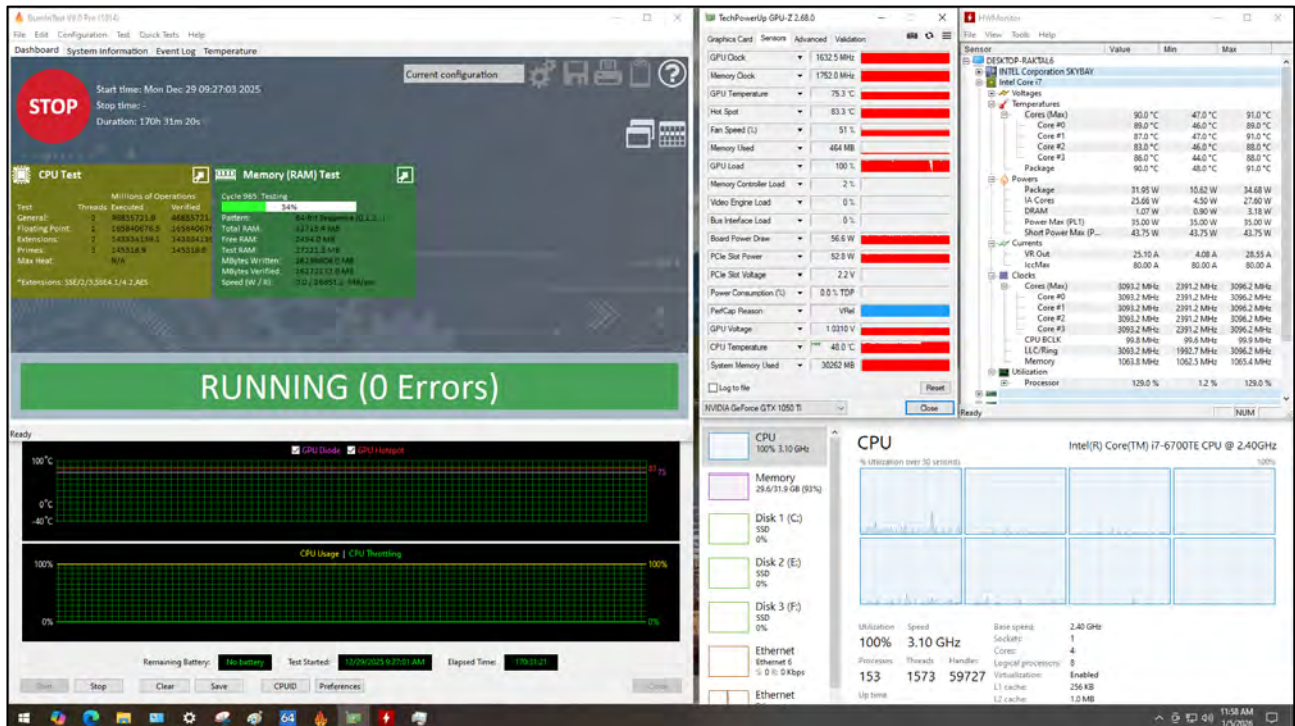




# PERFORMANCE TEST REPORT

## HORUS420-R1

### - Chamber in 60°C / 60%RH





## 4. THERMAL TEST RESULT(-40°C ~ +60°C)

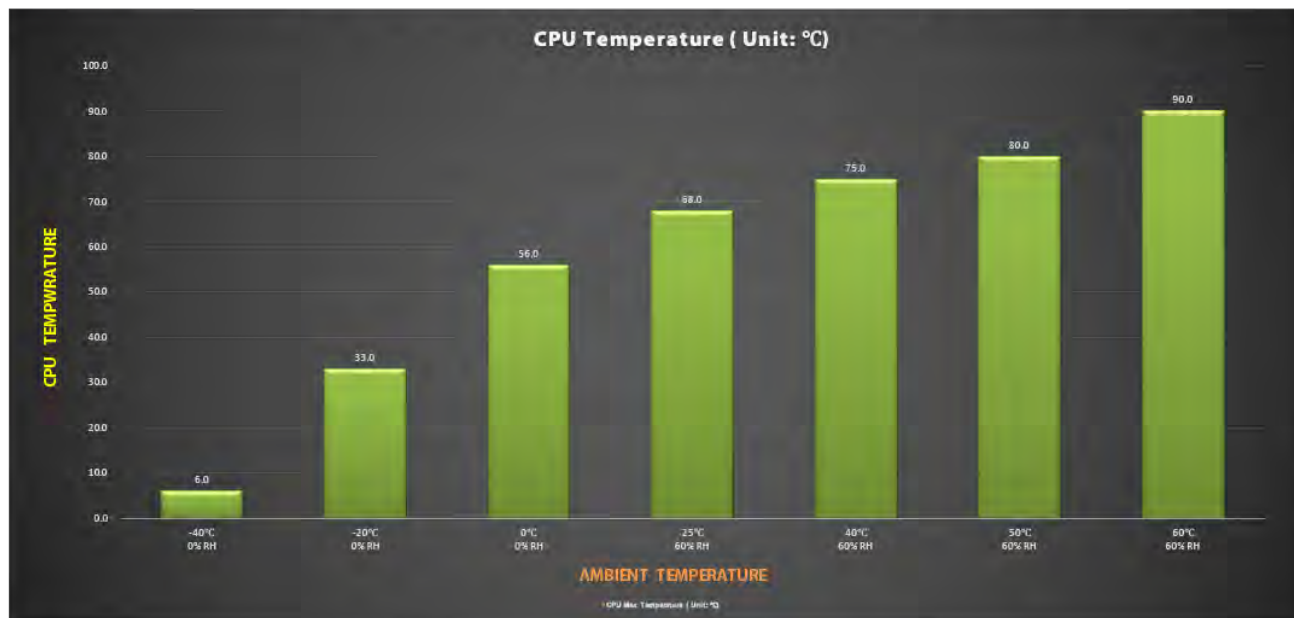
CPU & GPU Temperature and Frequency

| Temperature<br>Frequency             | Ambient Temp. | -40°C<br>0% RH | -20°C<br>0% RH | 0°C<br>0% RH | 25°C<br>60% RH | 40°C<br>60% RH | 50°C<br>60% RH | 60°C<br>60% RH |
|--------------------------------------|---------------|----------------|----------------|--------------|----------------|----------------|----------------|----------------|
| CPU Max Temperature ( Unit: °C)      |               | 6.0            | 33.0           | 56.0         | 68.0           | 75.0           | 80.0           | 90.0           |
| CPU Frequency (Unit: GHz)            |               | 3.10           | 3.10           | 3.10         | 3.10           | 3.10           | 3.10           | 3.10           |
| GPU Temperature ( Unit: °C)          |               | 9.3            | 13.8           | 25.2         | 38.5           | 54.1           | 64.6           | 75.3           |
| GPU Hot Spot Temperature ( Unit: °C) |               | 17.3           | 21.8           | 33.2         | 46.5           | 62.1           | 72.6           | 83.3           |
| GPU Frequency (Unit: MHz)            |               | 1721           | 1721           | 1709         | 1696           | 1671           | 1658           | 1633           |

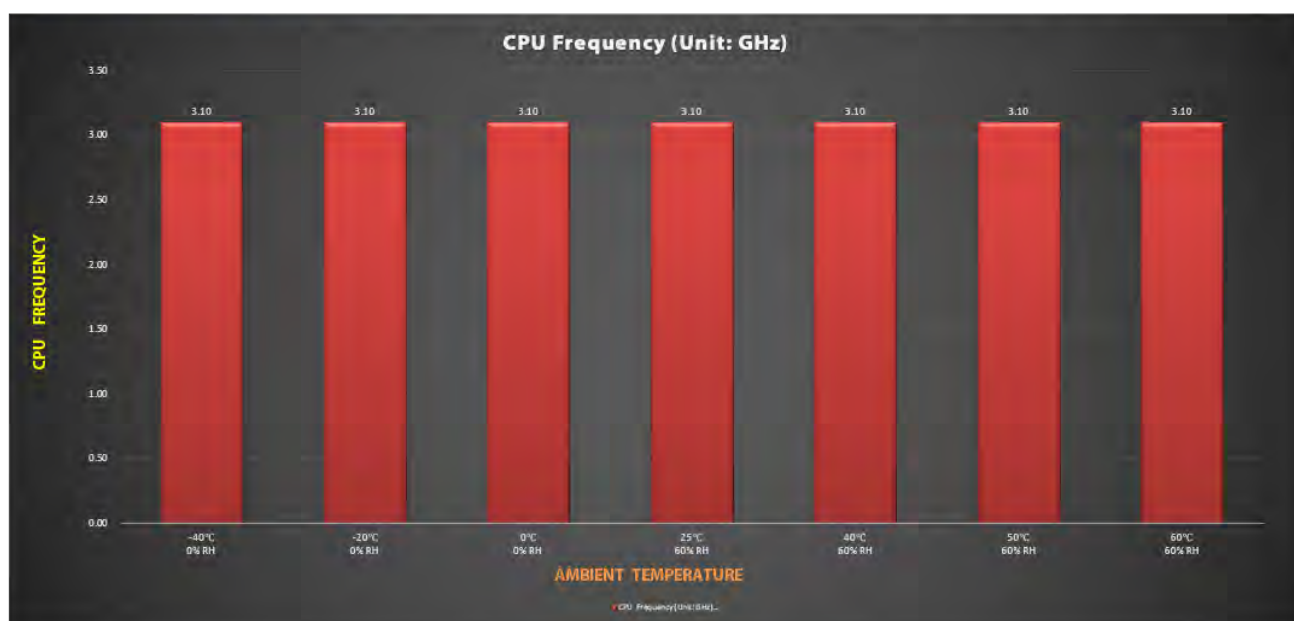
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| CPU Core<br>Temperature \ Ambient Temperature | -40°C<br>0% RH | -20°C<br>0% RH | 0°C<br>0% RH | 25°C<br>60% RH | 40°C<br>60% RH | 50°C<br>60% RH | 60°C<br>60% RH |
|---|----------------|----------------|--------------|----------------|----------------|----------------|----------------|
| CPU Max Temperature ( Unit: °C)               | 6.0            | 33.0           | 56.0         | 68.0           | 75.0           | 80.0           | 90.0           |



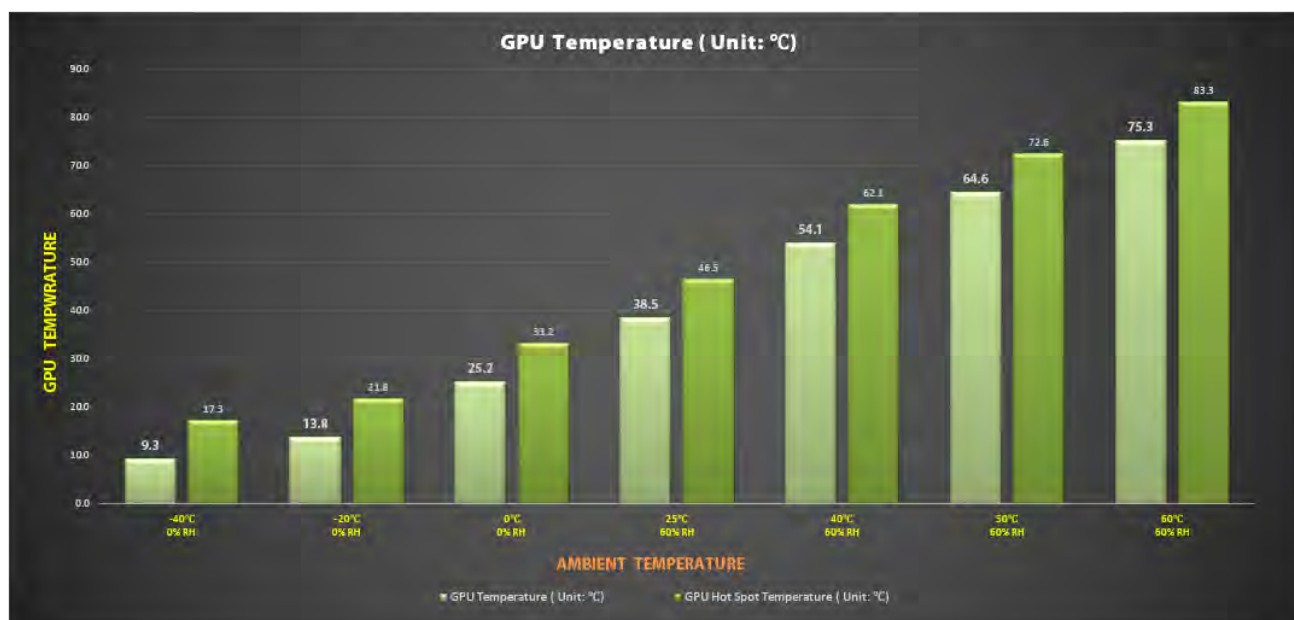
| CPU<br>Frequency \ Ambient Temperature | -40°C<br>0% RH | -20°C<br>0% RH | 0°C<br>0% RH | 25°C<br>60% RH | 40°C<br>60% RH | 50°C<br>60% RH | 60°C<br>60% RH |
|--|----------------|----------------|--------------|----------------|----------------|----------------|----------------|
| CPU Frequency (Unit: GHz)              | 3.10           | 3.10           | 3.10         | 3.10           | 3.10           | 3.10           | 3.10           |
| Processor Base Frequency: 2.40 GHz     |                |                |              |                |                |                |                |



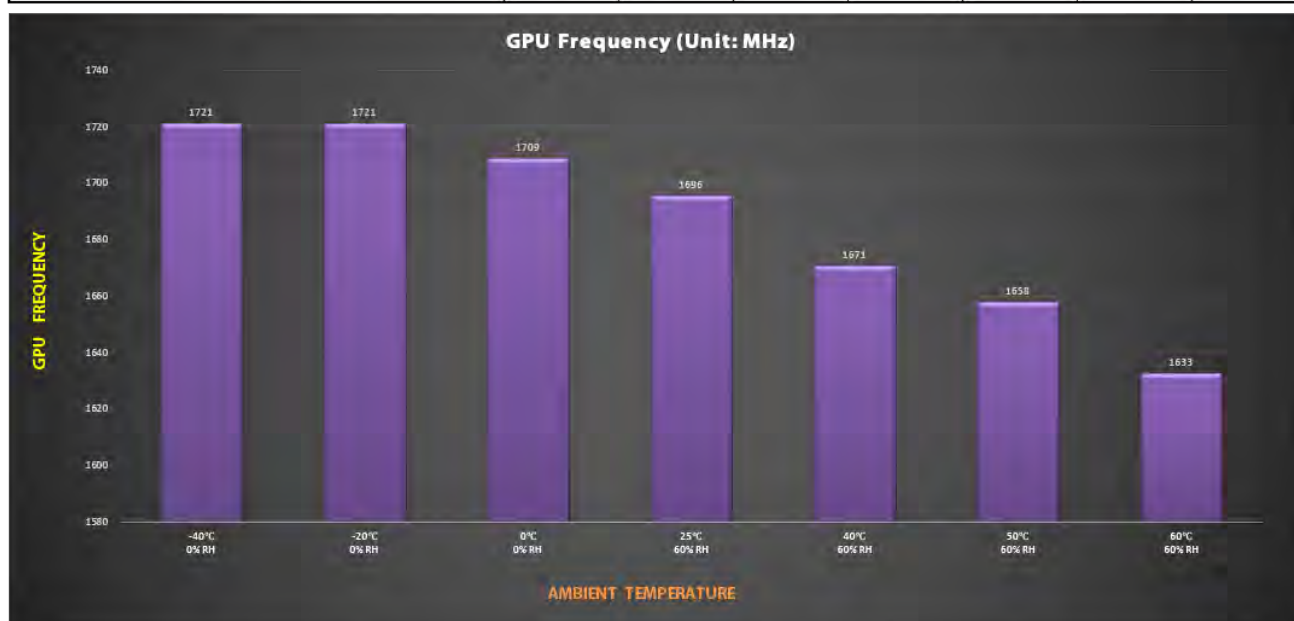
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| GPU<br>Temperature                   | Ambient Temperature | -40°C<br>0% RH | -20°C<br>0% RH | 0°C<br>0% RH | 25°C<br>60% RH | 40°C<br>60% RH | 50°C<br>60% RH | 60°C<br>60% RH |
|--------------------------------------|---------------------|----------------|----------------|--------------|----------------|----------------|----------------|----------------|
| GPU Temperature ( Unit: °C)          |                     | 9.3            | 13.8           | 25.2         | 38.5           | 54.1           | 64.6           | 75.3           |
| GPU Hot Spot Temperature ( Unit: °C) |                     | 17.3           | 21.8           | 33.2         | 46.5           | 62.1           | 72.6           | 83.3           |



| GPU<br>Frequency          | Ambient Temperature | -40°C<br>0% RH | -20°C<br>0% RH | 0°C<br>0% RH | 25°C<br>60% RH | 40°C<br>60% RH | 50°C<br>60% RH | 60°C<br>60% RH |
|---------------------------|---------------------|----------------|----------------|--------------|----------------|----------------|----------------|----------------|
| GPU Frequency (Unit: MHz) |                     | 1721           | 1721           | 1709         | 1696           | 1671           | 1658           | 1633           |





## 5. I/O FUNCTION TEST

### 5-1. LAN PORT

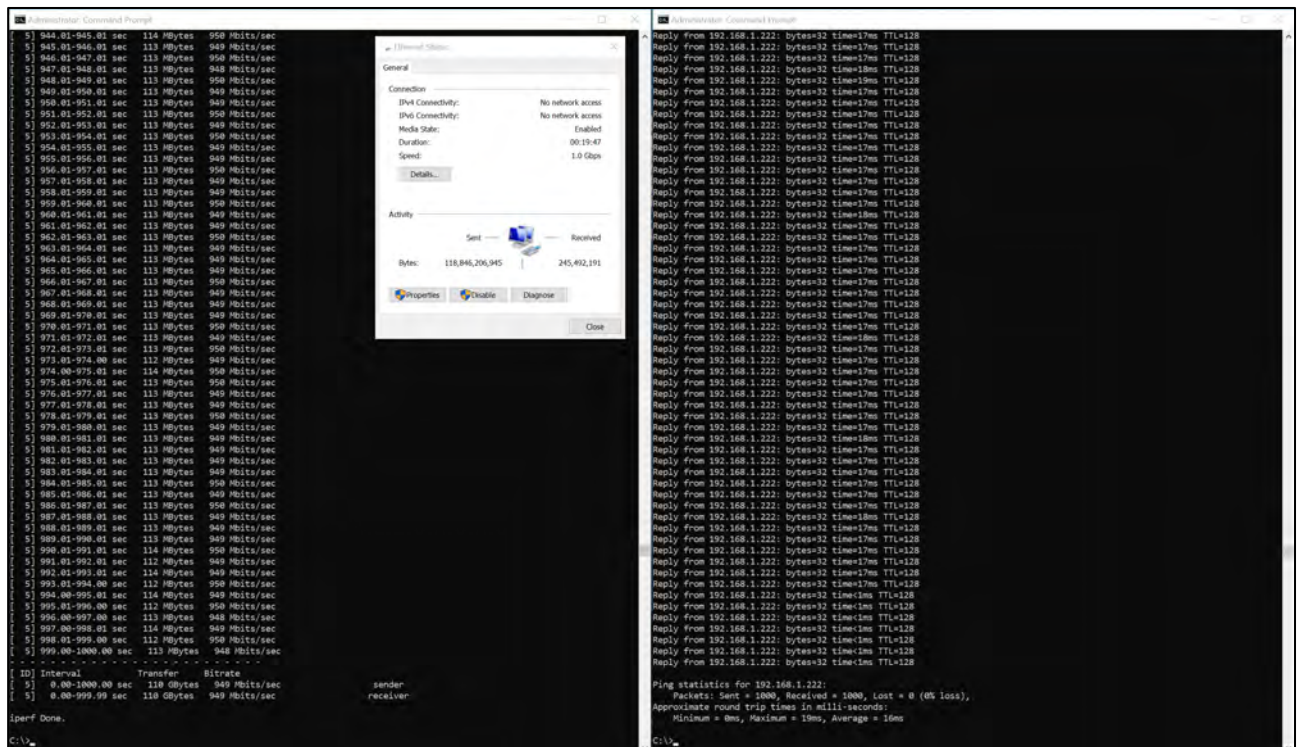


1GbE

LAN SPEED

LAN Data-Packet

LAN 1



LAN Speed Test Result: Pass

LAN Data-Packet Test Result: 0 Lost (0% loss)

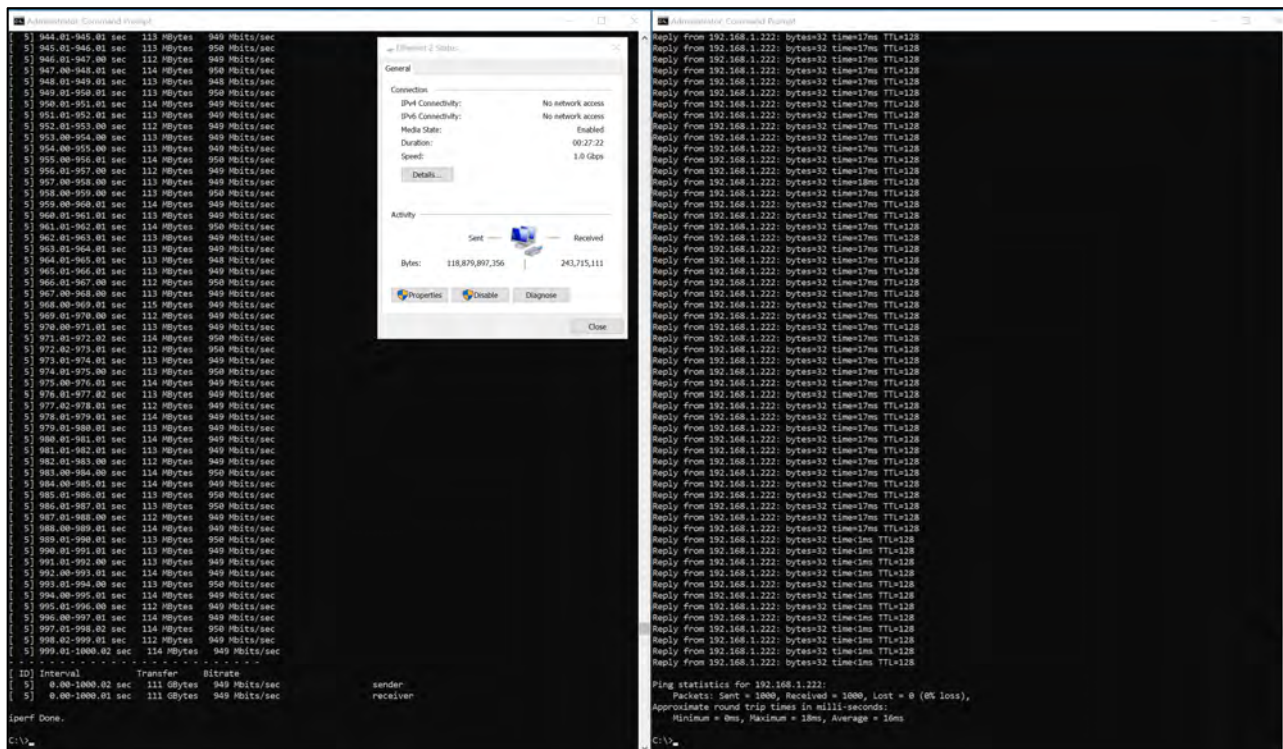
# PERFORMANCE TEST REPORT

## HORUS420-R1

### LAN SPEED

### LAN Data-Packet

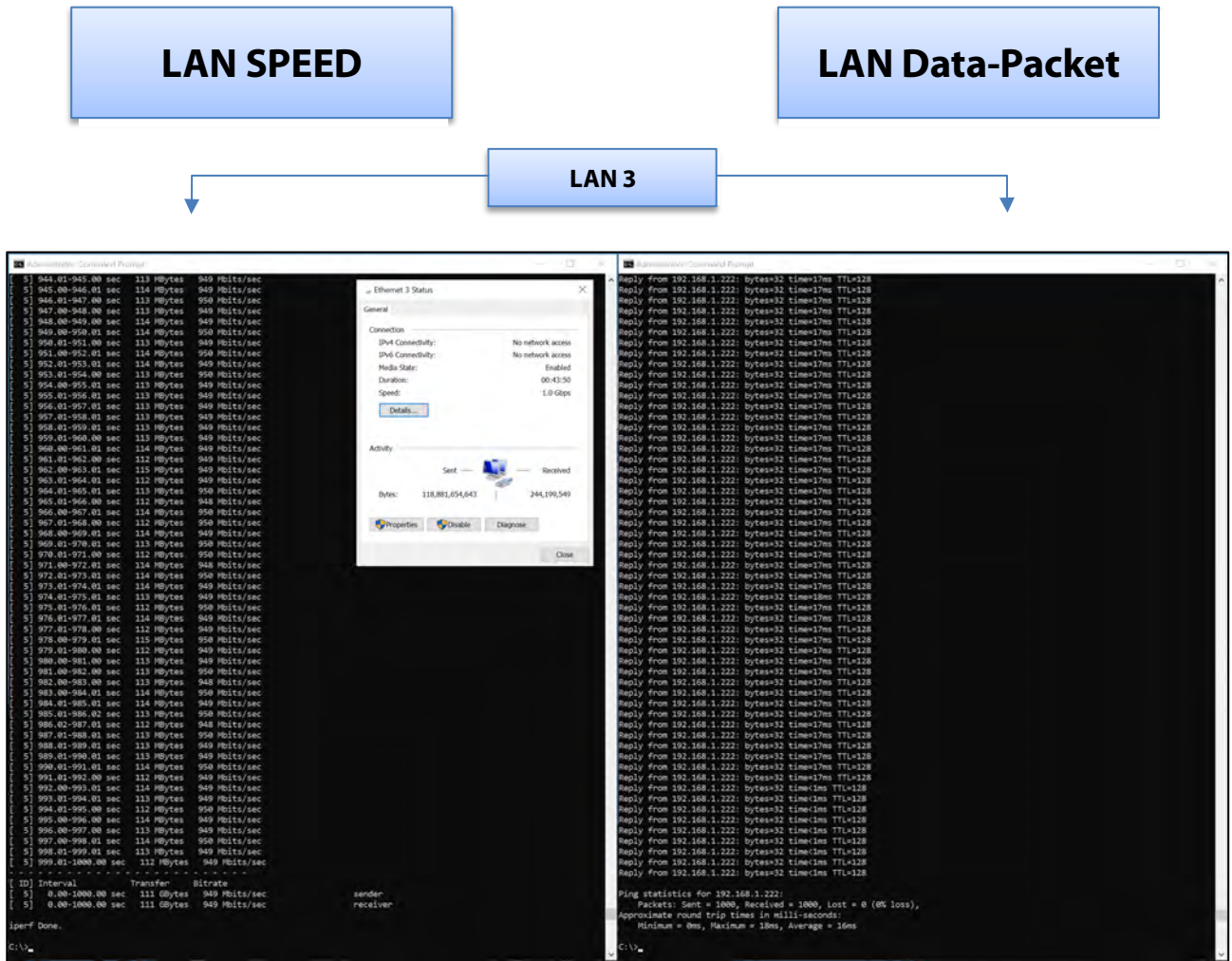
LAN 2



**LAN Speed Test Result: Pass**  
**LAN Data-Packet Test Result: 0 Lost (0% loss)**



# HORUS420-R1



## LAN Data-Packet Test Result: 0 Lost (0% loss)

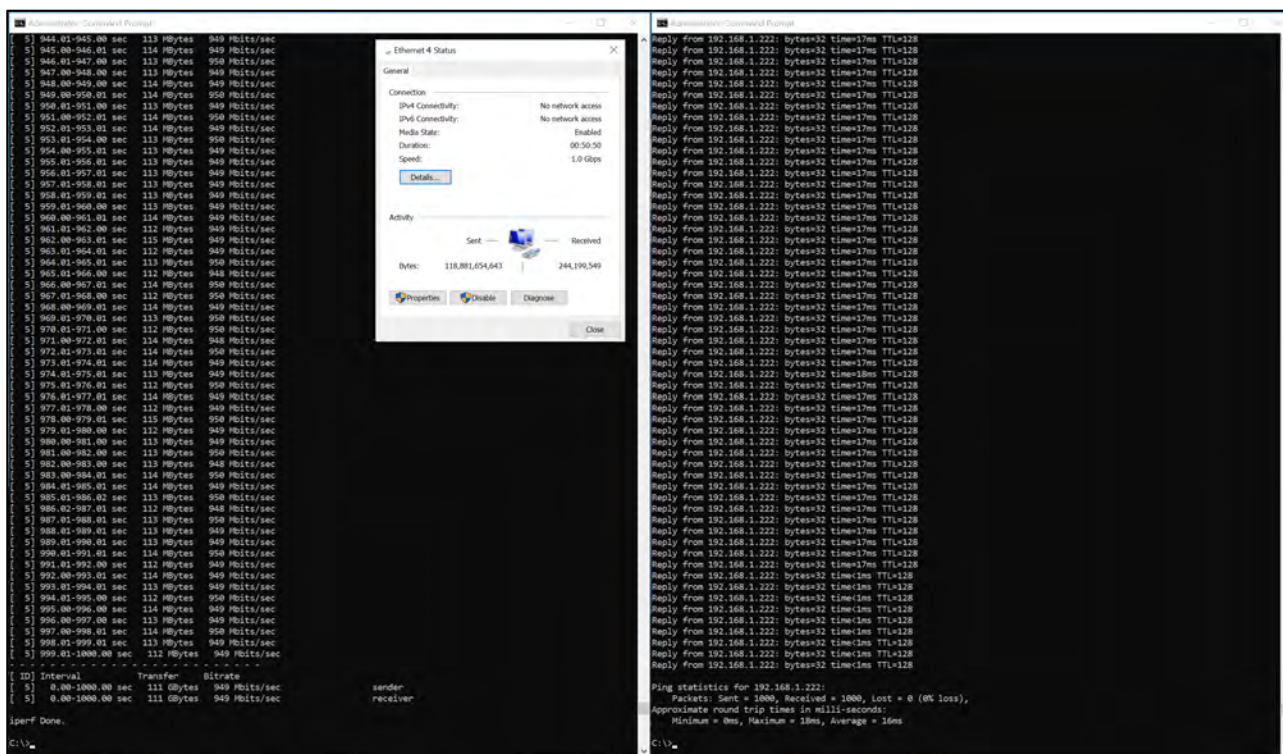
# PERFORMANCE TEST REPORT

## HORUS420-R1

### LAN SPEED

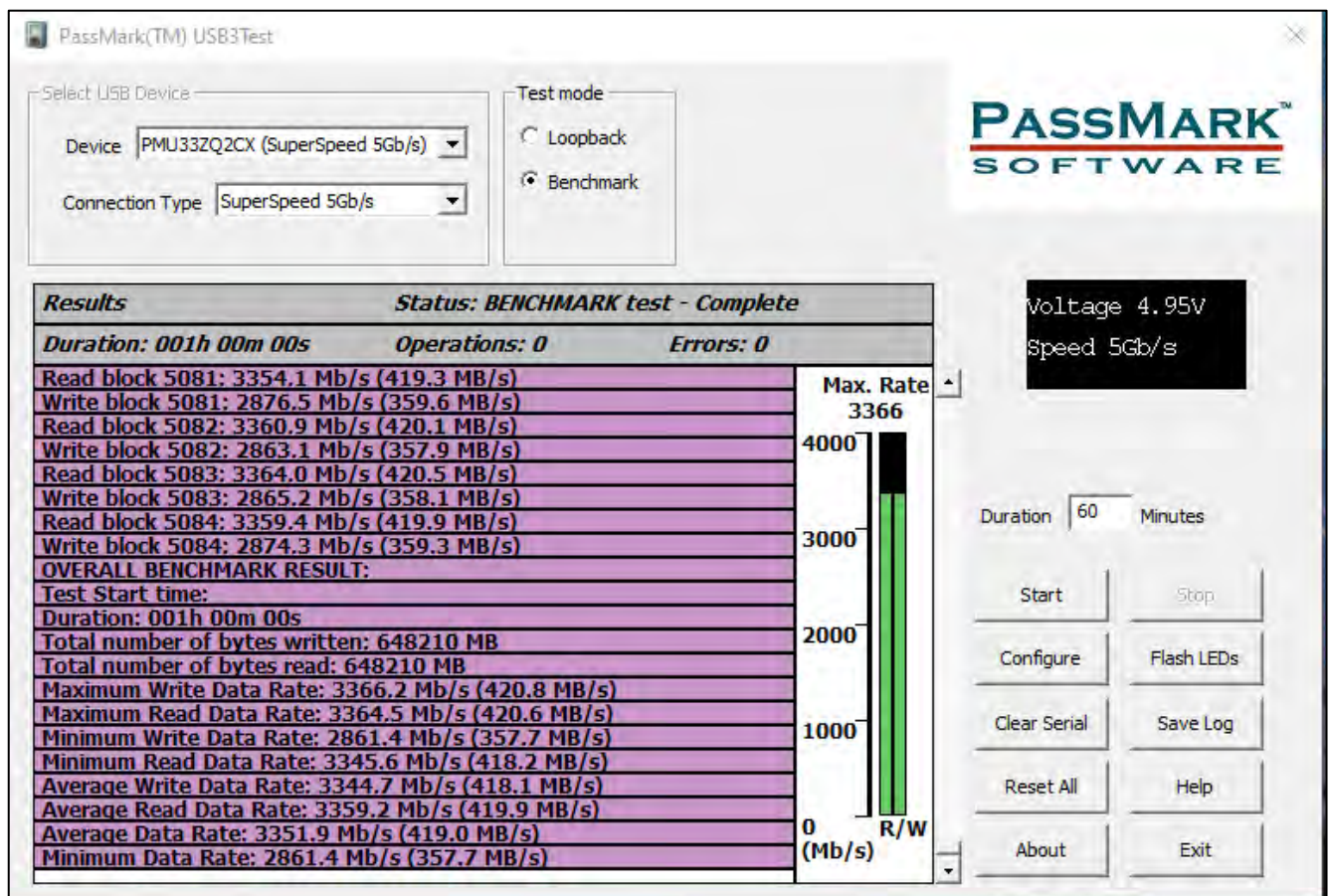
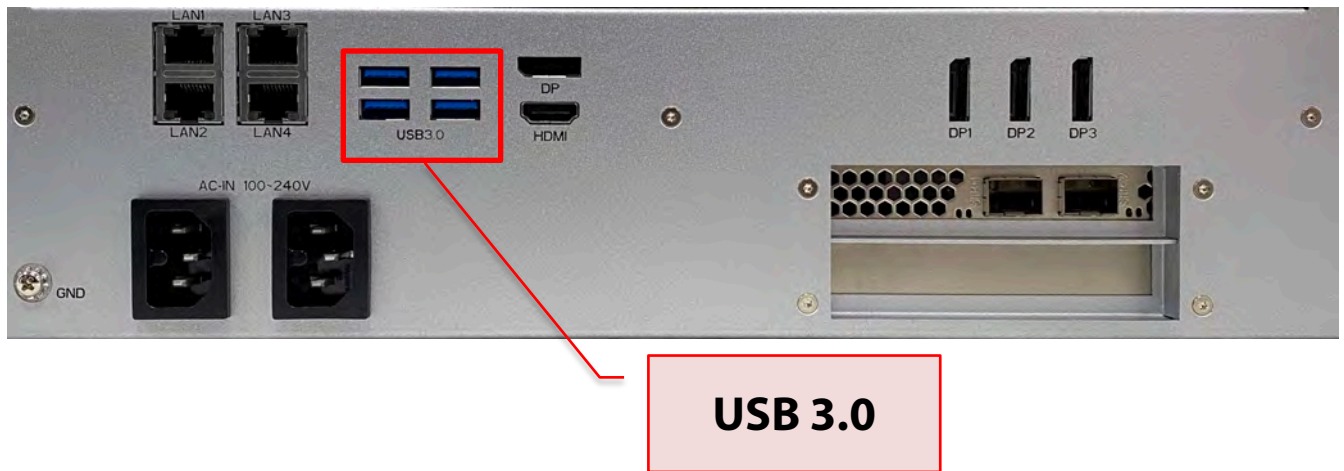
### LAN Data-Packet

LAN 4



**LAN Speed Test Result: Pass**  
**LAN Data-Packet Test Result: 0 Lost (0% loss)**

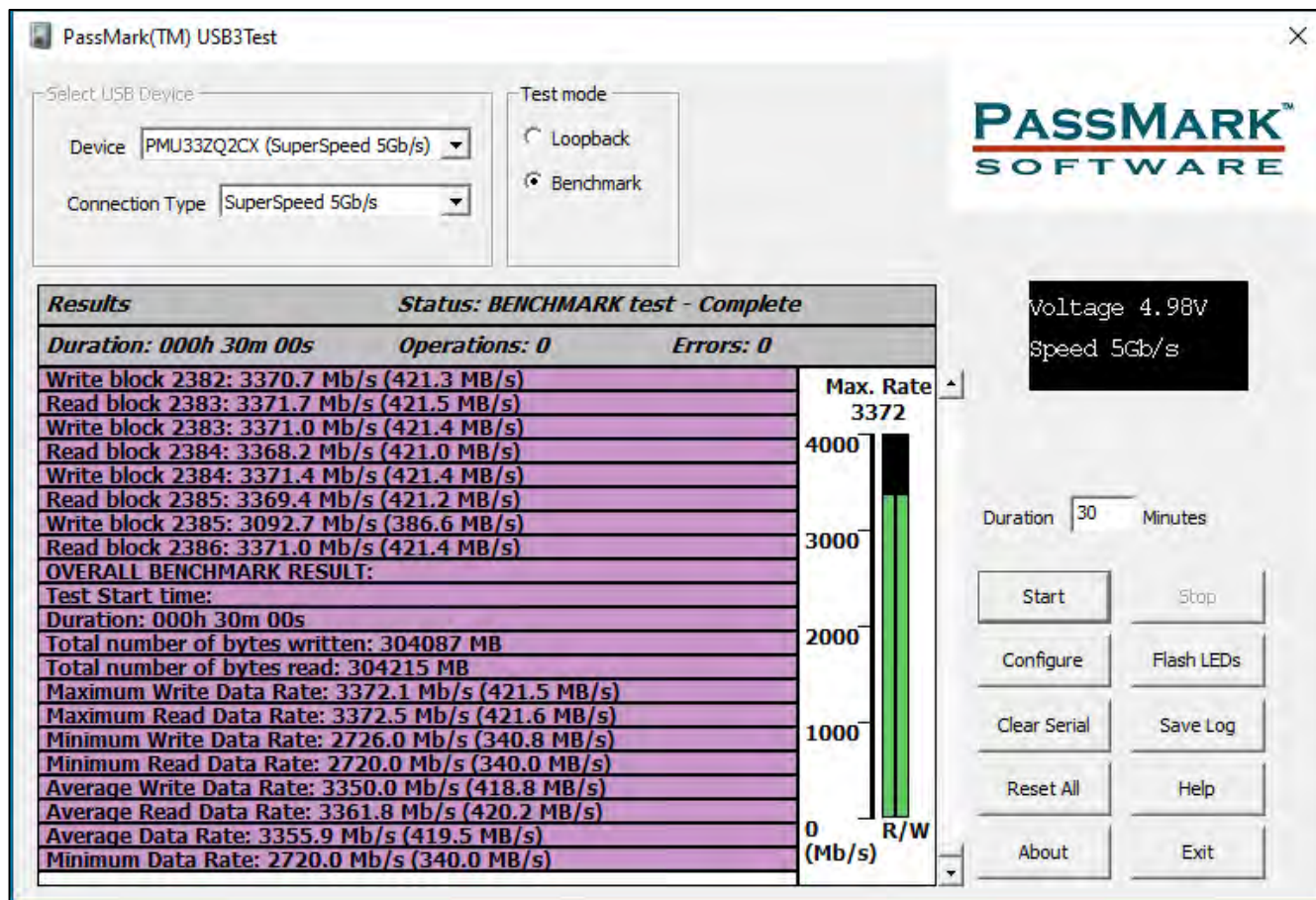
## 5-2. USB PORT(REAR)





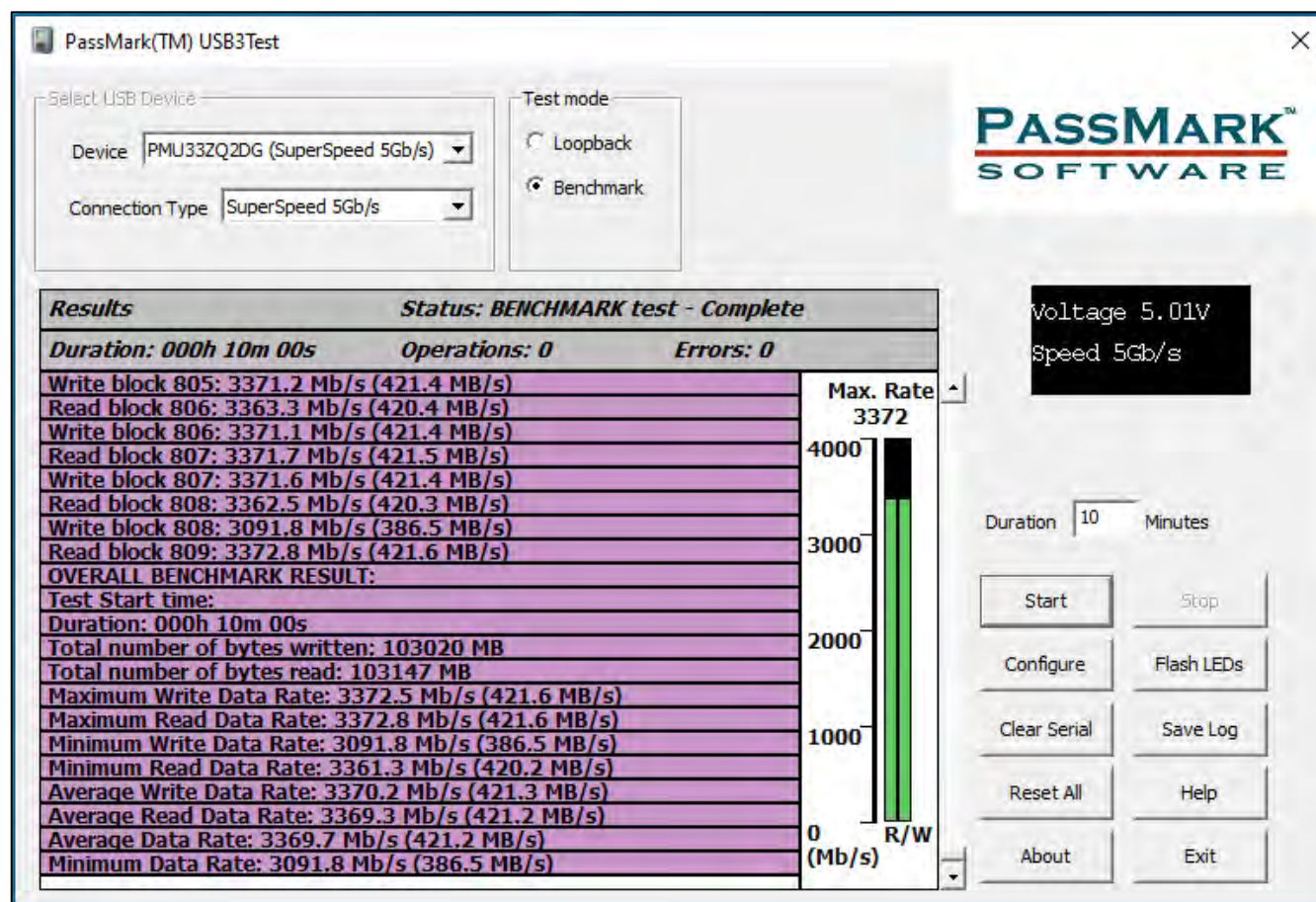
# PERFORMANCE TEST REPORT

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# PERFORMANCE TEST REPORT

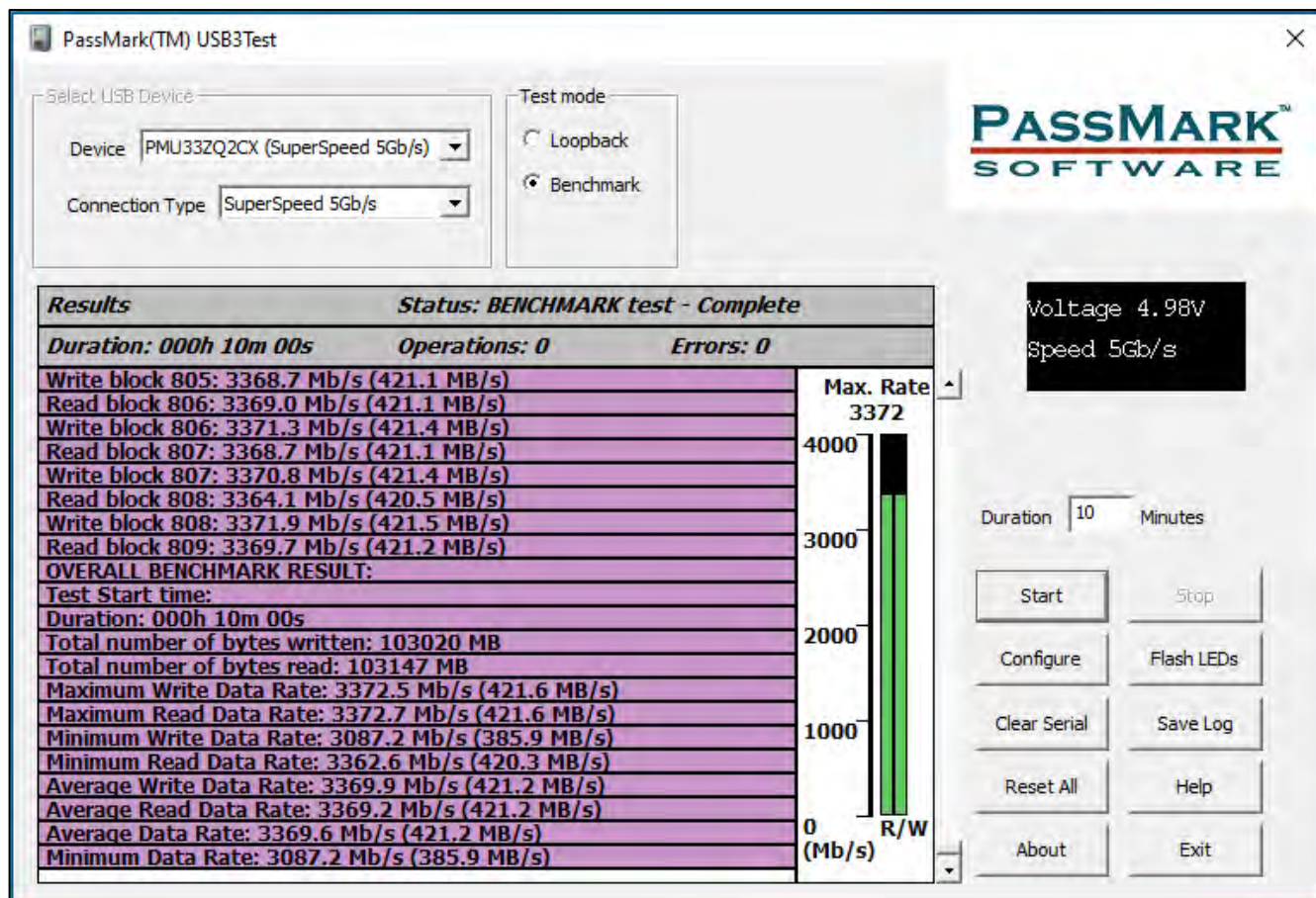
## HORUS420-R1





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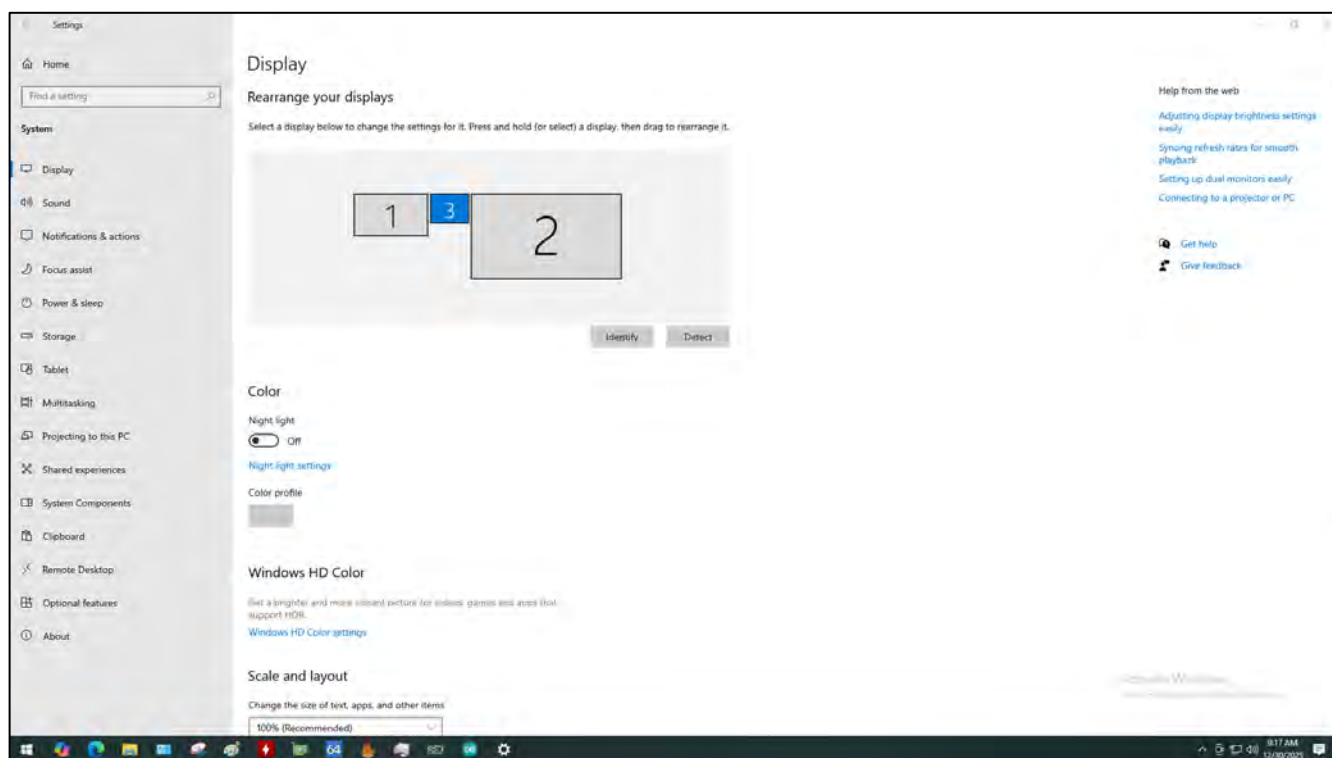
## HORUS420-R1



### 5-3. DISPLAY PORT



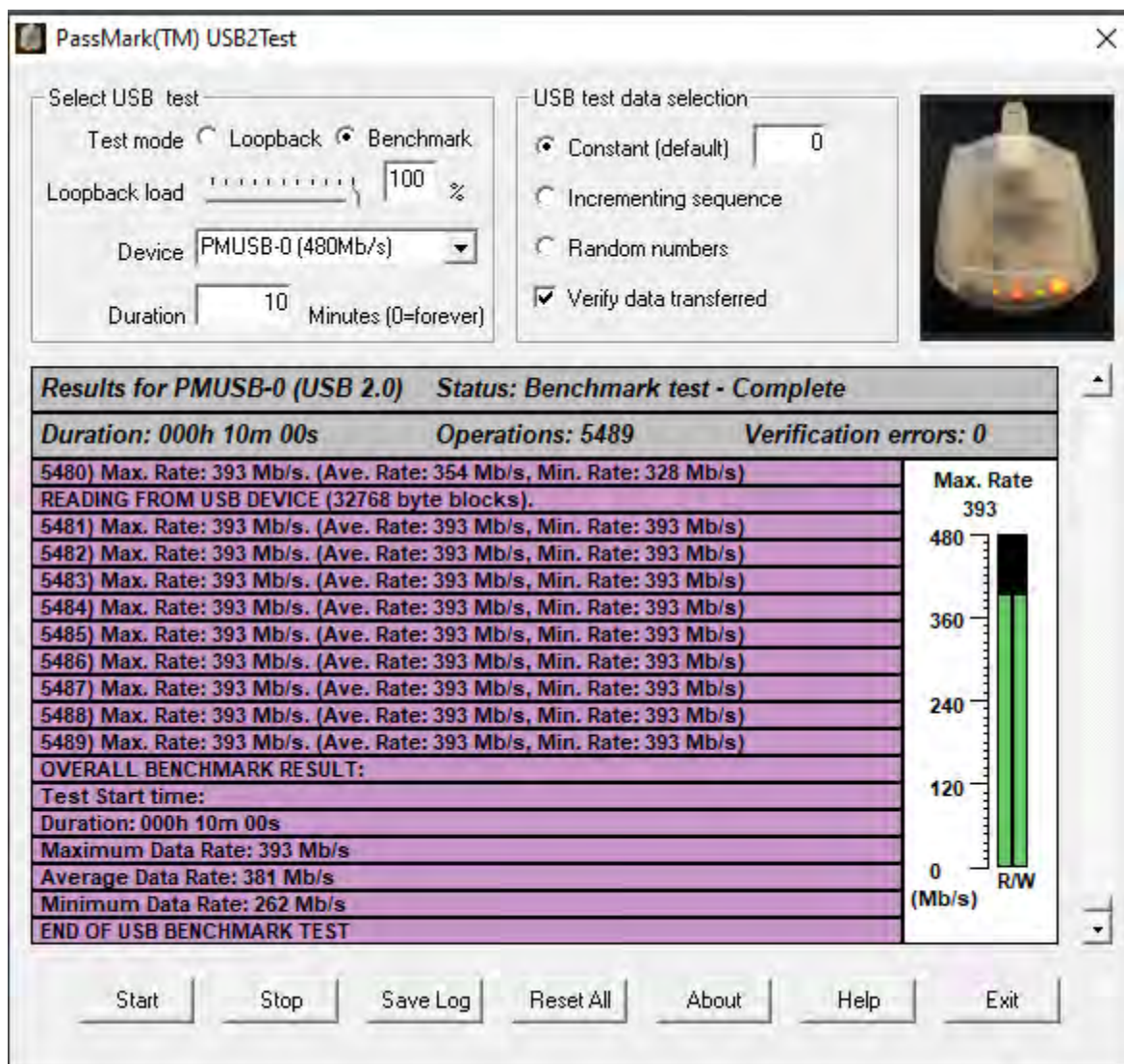
DP



## 5-4. USB PORT (FRONT)



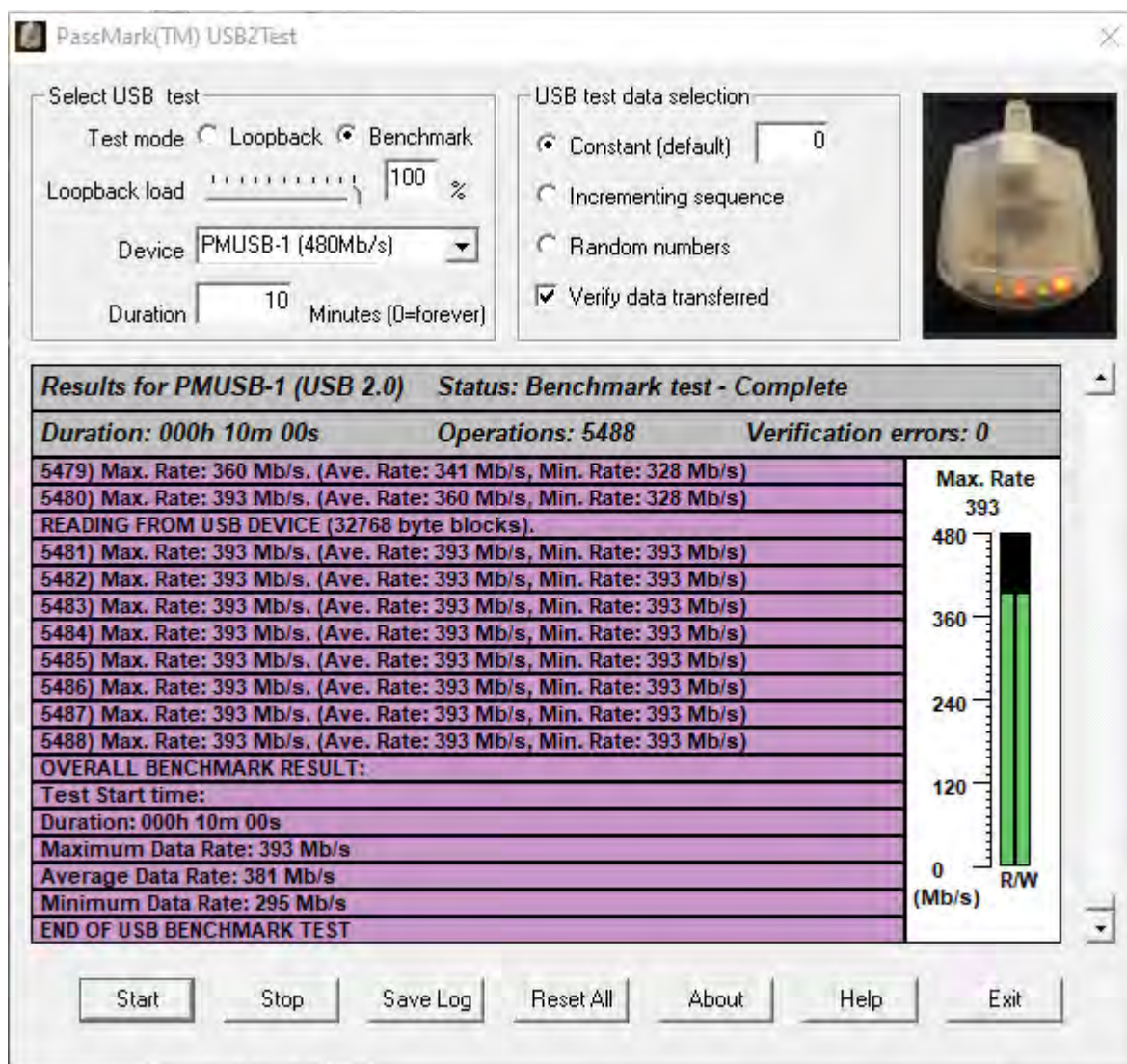
USB 2.0





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S/N: SR2025100902

| Product Manager | Mechanical Engineer | System Engineer | Test Engineer |
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| Honwen Huang    | Jeff Lin            | Orpheus Hsiung  | Mike Chen     |

Date: January 27, 2026

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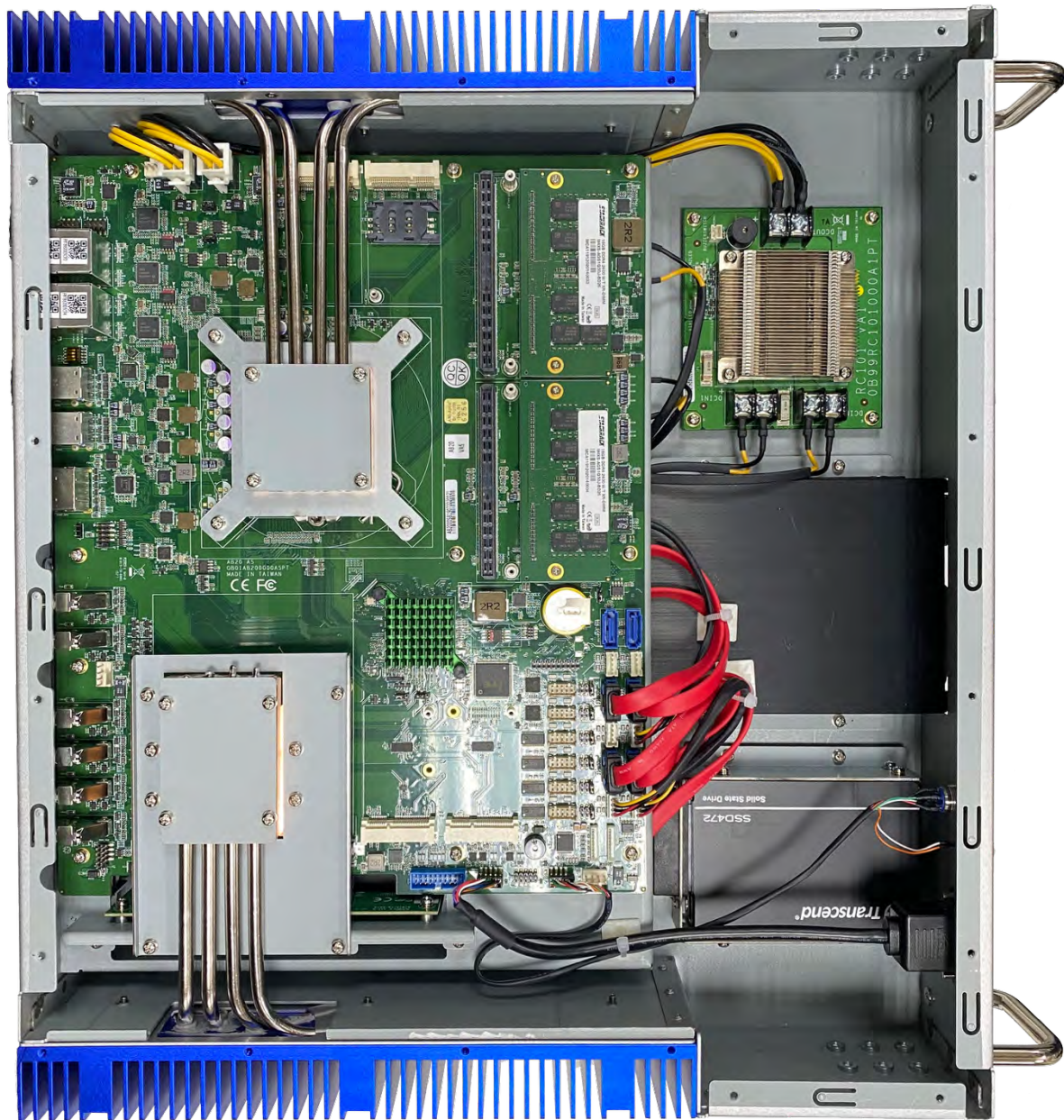


# 1. SPECIFICATION

## 1-1. SYSTEM CONFIGURATION

|                     |   |
|---------------------|---|
| <b>Motherboard</b>  | AB20<br>BIOS Version: 5.11<br>SMBIOS Version: 3.0<br>Supports Intel® LGA 1151 14nm Skylake-S Processor<br>Operating Temp. -40°C~85°C  |
| <b>CPU</b>          | Intel® Core™ i7-6700TE Processor<br>Total Cores: 14<br>Total Cores: 4<br>Total Threads: 8<br>Max Turbo Frequency: 3.40 GHz<br>Intel® Turbo Boost Technology 2.0 Frequency†: 3.40 GHz<br>Processor Base Frequency: 2.40 GHz<br>TDP: 35 W |
| <b>Memory</b>       | 32GB DDR4 XR-DIMM   |
| <b>Storage</b>      | Internal: 2TB *2 3D TLC SSD<br>External: 2TB *2 3D TLC SSD  |
| <b>GPU</b>          | NVIDIA GeForce GTX 1050 Ti Embedded GPU<br>BIOS Version: 86.07.59.00.E3<br>CUDA parallel-processing cores: 768 CUDA® cores<br>GPU base/boost clock: 1291 MHz / 1392 MHz<br>Max Power Consumption: 75 W                                  |
| <b>Add-on cards</b> | Perfectron MT201 Intel® 82599ES 10Gb/s 2 x LAN port<br>2 x SFP+ LAN ports<br>Supports 10Gb/s per port<br>Intel® 82599ES<br>PCIe x8 (Gen2 x8 bus)  |
| <b>Power Module</b> | 2 x 200W AC-DC PSU With redundant Power   |

## 1-2. PRODUCT INTERIOR PHOTO



## 2. TEST PLAN

### 2-1. THERMAL MEASUREMENT PROCESS

|                               |   |
|-------------------------------|---|
| <b>Test Purpose</b>           | <p>The purpose of conducting thermal profile testing is to identify potential thermal issues in the Equipment Under Test (EUT). Given that semiconductor failure rates increase significantly with rising junction temperatures, this testing contributes to the overall assessment of product reliability.</p> <p>As the system undergoes a cooling phase, operational modes may shift depending on stack configuration, temperature, and heat dissipation characteristics. Thermal mapping provides critical insight for optimizing thermal management strategies and determining the most effective component layout and monitoring arrangements.</p>  |
| <b>Test Equipment</b>         | 1. KSON THS-B4T-150 Chamber.  |
| <b>Quantity Tested</b>        | Minimum 1 Set   |
| <b>Test Software</b>          | <p>CPU Stress: PassMark BurnIn Test v9.0</p> <p>GPU Stress: AIDA64 Business v6.90</p> <p>LAN Speed Test: iPerf3</p>   |
| <b>Test Procedure</b>         | <p>1. Thermal Pre-Scan Measurement:<br/> Temperature Range: <b>-40°C to 60°C</b><br/> Humidity Condition: <b>60% RH</b> (when temperature exceeds 25°C)</p> <p>2. Actual Thermal Measurement Procedure:</p> <p>2.1. Identify the test points using the infrared thermal image and attach thermocouples to the identified hot spots.</p> <p>2.2. Place the Equipment Under Test (EUT) in the thermal chamber and configure the test temperature profile according to the specified requirements.</p> <p>2.3. Power on the EUT after closing the thermal chamber. Boot into Windows 11 Pro and initiate a maximum power consumption and stress test.</p> <p>2.4. After running the test software continuously for 8 hours, record the peak temperature observed at each thermocouple measurement point.</p> <p>2.5. Power off both the thermal chamber and the EUT.</p> <p>2.6. Verify that the recorded temperature data for each component remains within its specified operating temperature range, as defined in the component specification or approval documents.</p> |
| <b>Test Diagram of Curves</b> | <p>Environment defines for 174 hours.</p> <p>The graph displays two curves over a 174-hour period. The left Y-axis represents Temperature in degrees Celsius (°C), ranging from -40 to 60. The right Y-axis represents Humidity in percent relative humidity (%RH), ranging from 0% to 60%. The X-axis represents Time in hours, ranging from 0 to 174. The Temperature testing period (red line) starts at 25°C, drops to -40°C at 1.0 hour, stays at -40°C until 24.0 hours, then rises to 74.0°C at 50.0 hours. The Humidity testing period (blue line) starts at 0% RH, rises to 60% RH at 75.0 hours, stays at 60% RH until 174.0 hours, and then drops to 25% RH. The graph shows a complex thermal profile with multiple temperature steps and a humidity ramp.</p>  |



## 2-2. TEST RESULT

### 2-2-1. Temperature Cycle

# Aging tests were performed on individual components across a range of temperature settings, under both maximum load and full load conditions, to evaluate thermal endurance and operational stability over time.

| Test Temperature | Test Result |
|------------------|-------------|
| -40°C / 0%RH     | PASS        |
| -20°C / 0%RH     | PASS        |
| 0°C / 0%RH       | PASS        |
| 25°C / 60%RH     | PASS        |
| 40°C / 60%RH     | PASS        |
| 50°C / 60%RH     | PASS        |
| 60°C / 60%RH     | PASS        |

### 2-2-2. I/O Function

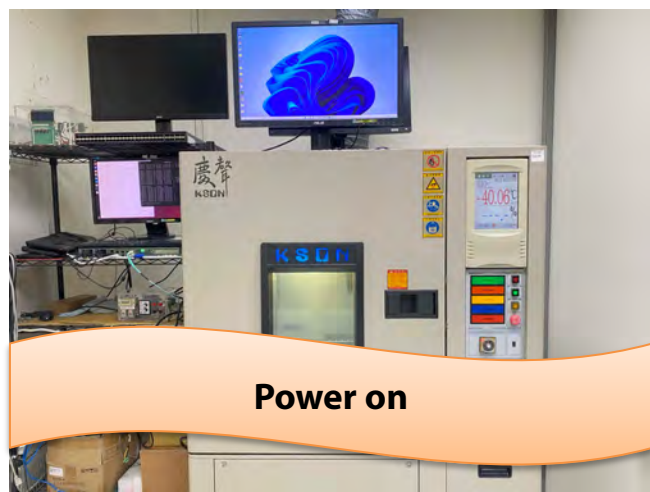
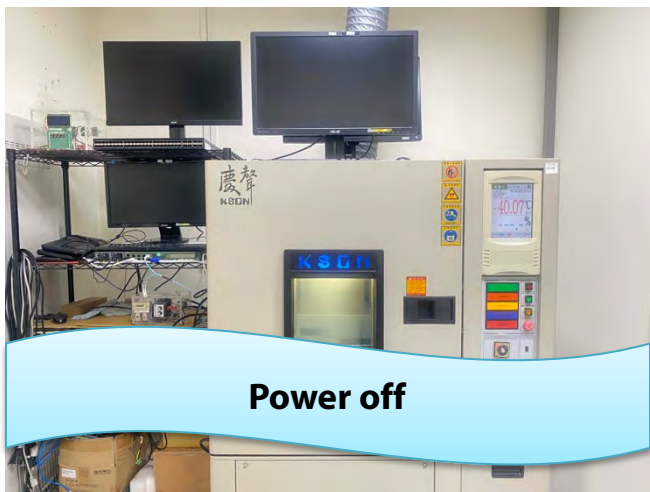
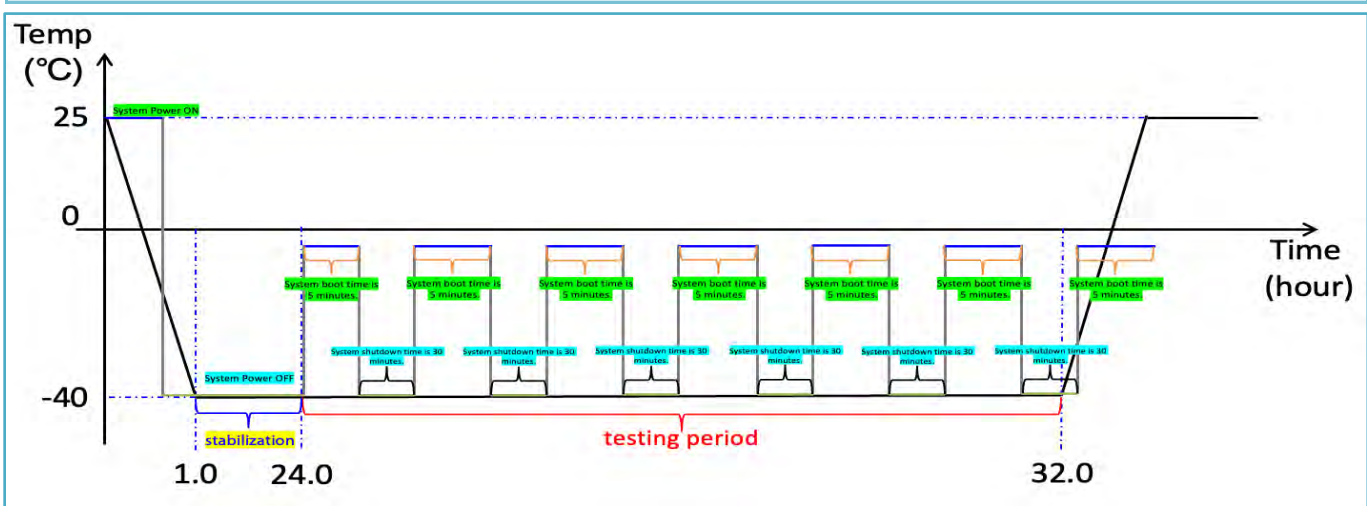
# Confirm that the system specifications and all input/output (I/O) interfaces are correctly configured and functioning as intended, in accordance with the defined technical standards.

| Item                | Test Criteria  | Result      |
|---------------------|--|-------------|
| <b>USB 2.0</b>      | A PassMark USB_2.0 Loopback was connected for testing and was found to be functioning normally.  | <b>PASS</b> |
| <b>USB 3.0</b>      | A PassMark USB_3.0 Loopback was connected for testing and was found to be functioning normally.  | <b>PASS</b> |
| <b>Display Port</b> | The DP output has been verified to be working properly, and the resolution can be adjusted according to the monitor size.  | <b>PASS</b> |
| <b>1GbE LAN</b>     | Data transmission via connection to a 1 Gbps LAN switch has been tested. The transfer speed meets the required standard with zero packet loss, confirming normal functionality.  | <b>PASS</b> |
| <b>10GbE LAN</b>    | Data transmission via connection to a 10 Gbps LAN switch has been tested. The transfer speed meets the required standard with zero packet loss, confirming normal functionality. | <b>PASS</b> |

### 2-2-3. Low Temperature Power Cycle Test

# Apply power to the system under a -40°C ambient condition and confirm successful system boot-up, ensuring stable initialization and operation at low temperatures.

| Ambient Temp. | Cold Boot Test Times | Test Result |
|---------------|----------------------|-------------|
| -40°C         | 125 times            | PASS        |



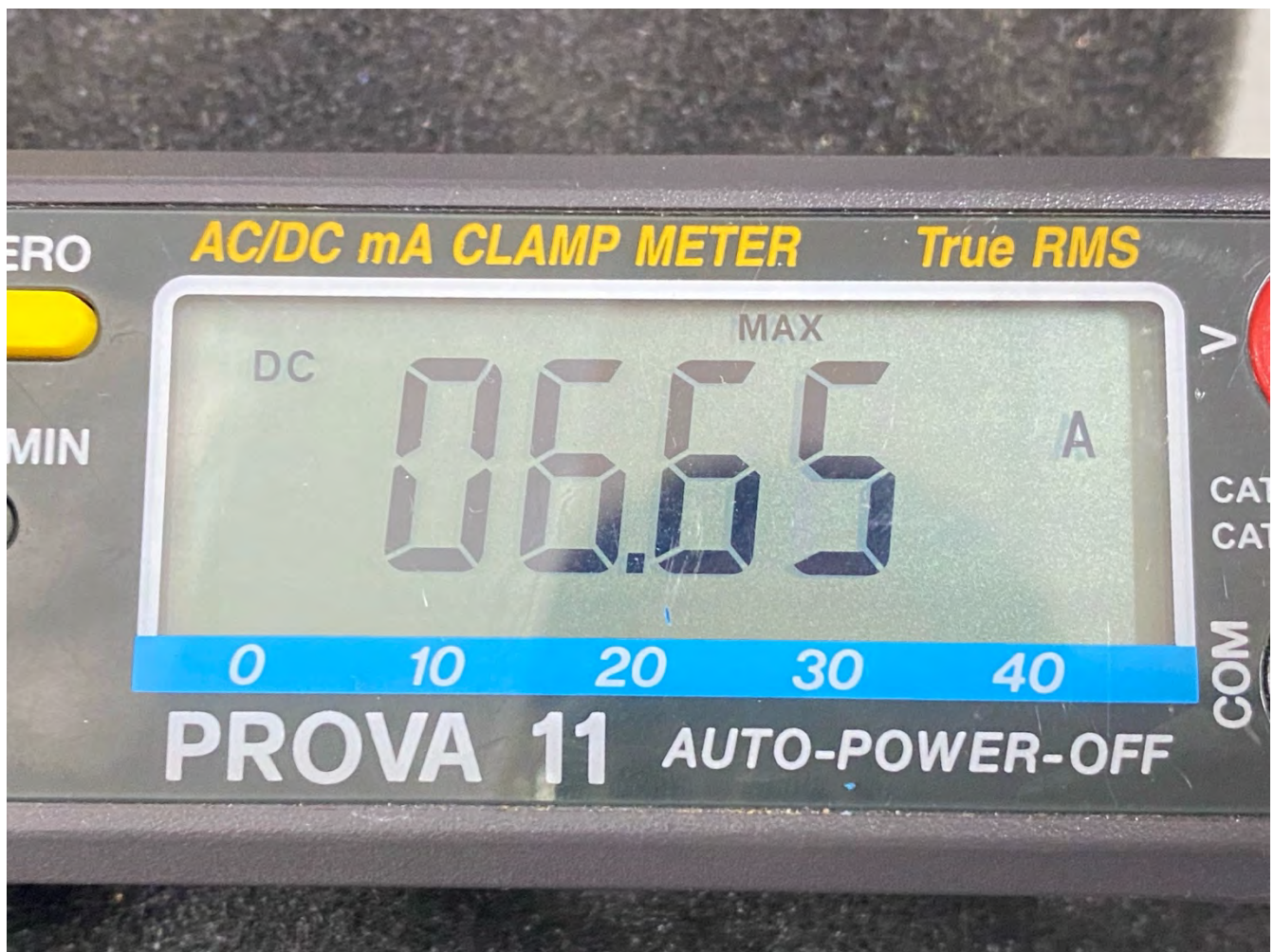


## 2-3. PEAK INSTANTANEOUS CURRENT AND POWER

Maximum instantaneous current and power measured during the entire period from system power-on to operating system initialization.

The current value was measured at the output terminal of the internal DC-DC redundant board.

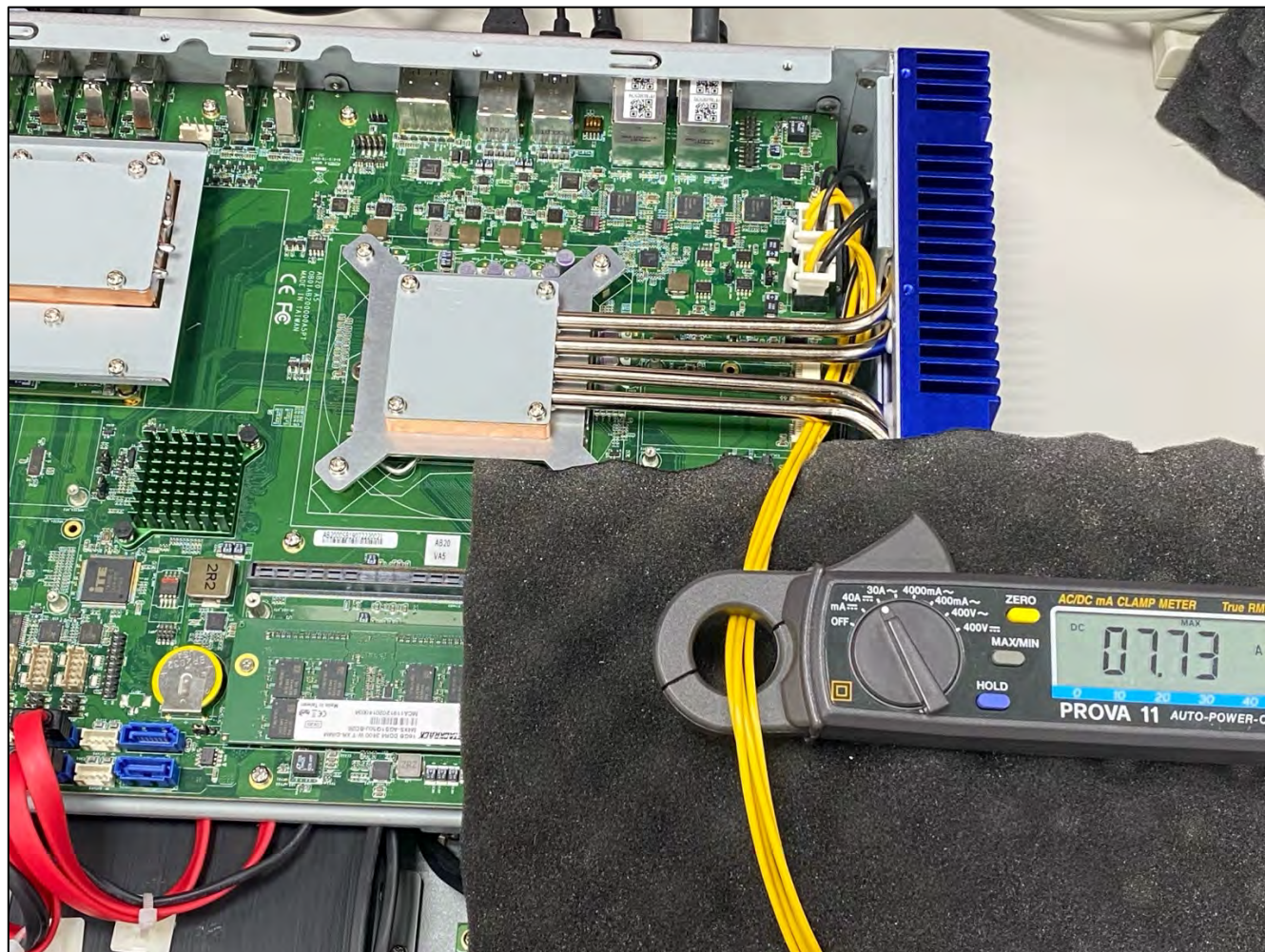
| Voltage (V) | Peak Instantaneous Current (A) | Peak Instantaneous Power (W) |
|-------------|--------------------------------|------------------------------|
| 12.0        | 6.65                           | 79.8                         |



## 2-4. POWER CONSUMPTION

**The current value was measured at the output terminal of the internal DC-DC redundant board.**

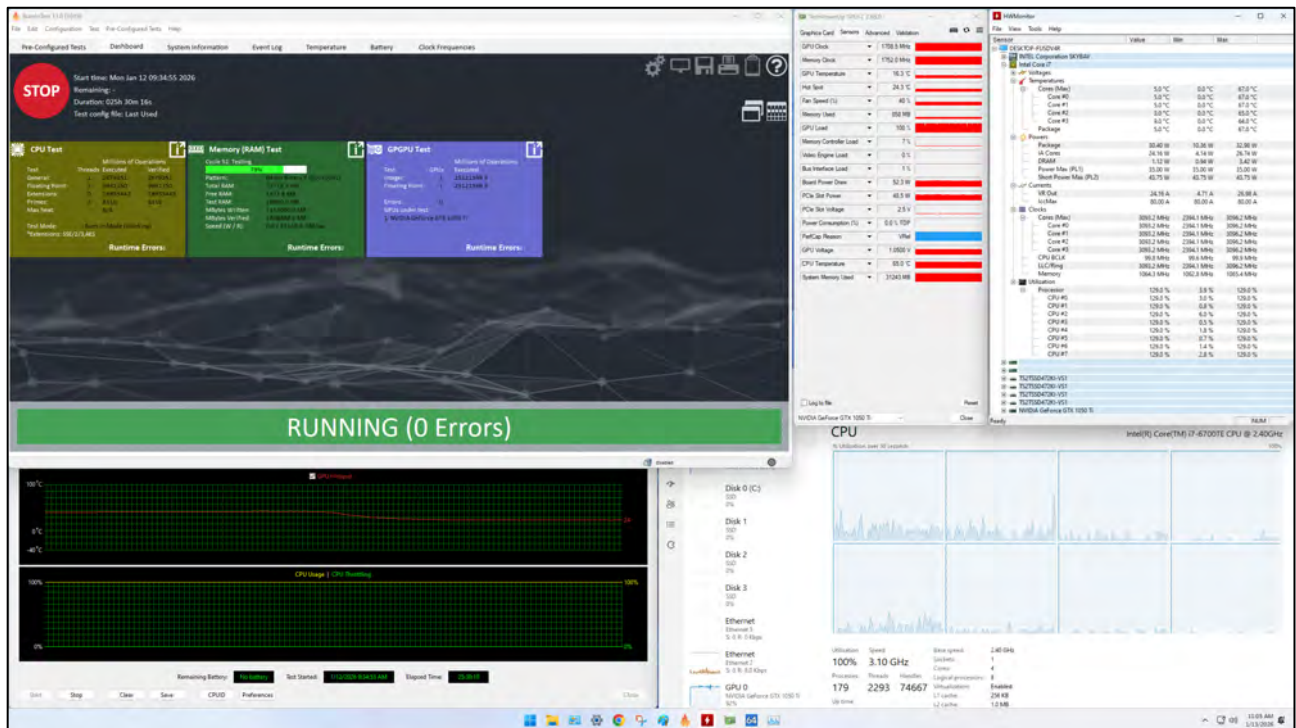
| Voltage (V) | Current (A) | Wattage (W) |
|-------------|-------------|-------------|
| 12.0        | 7.73        | 92.76       |





### 3. TEST PHOTO IN LAB

- Chamber in -40°C / 0%RH

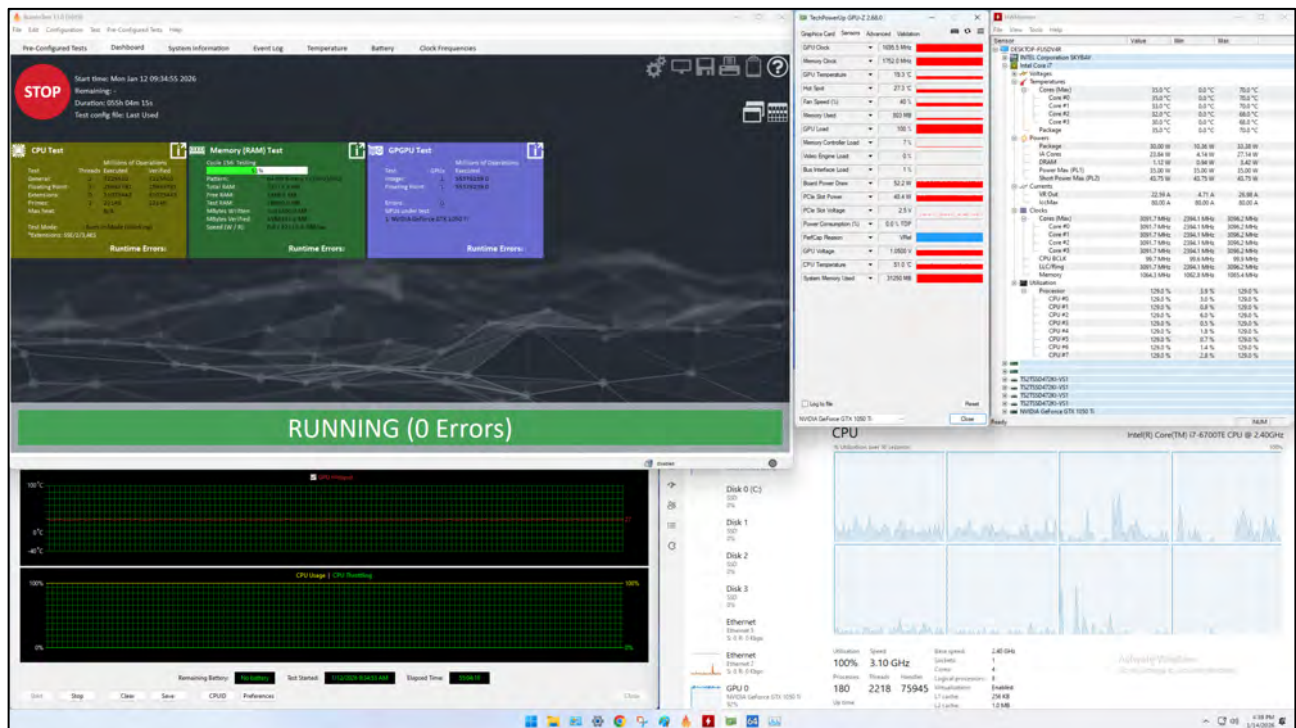




# PERFORMANCE TEST REPORT

## HORUS420-R1

- Chamber in -20°C / 0%RH



**- Chamber in 0°C / 0%RH**

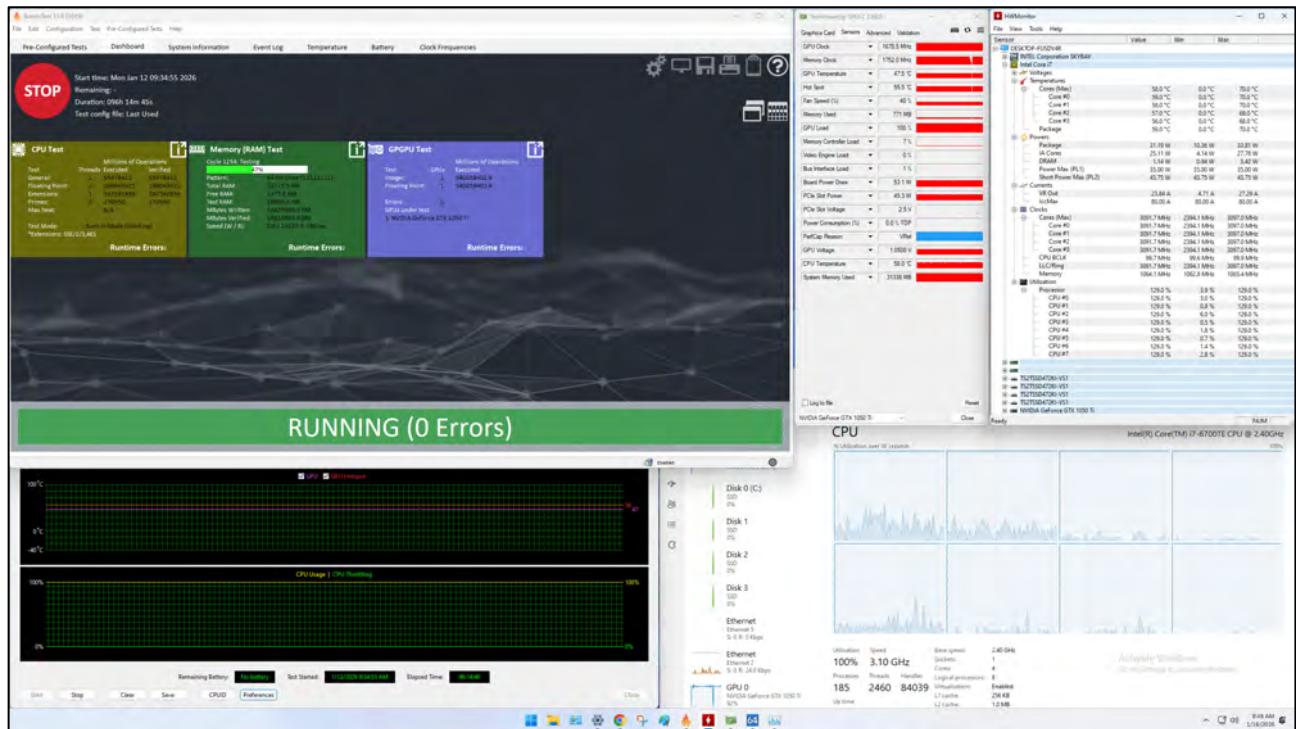




# PERFORMANCE TEST REPORT

## HORUS420-R1

### - Chamber in 25°C / 60%RH

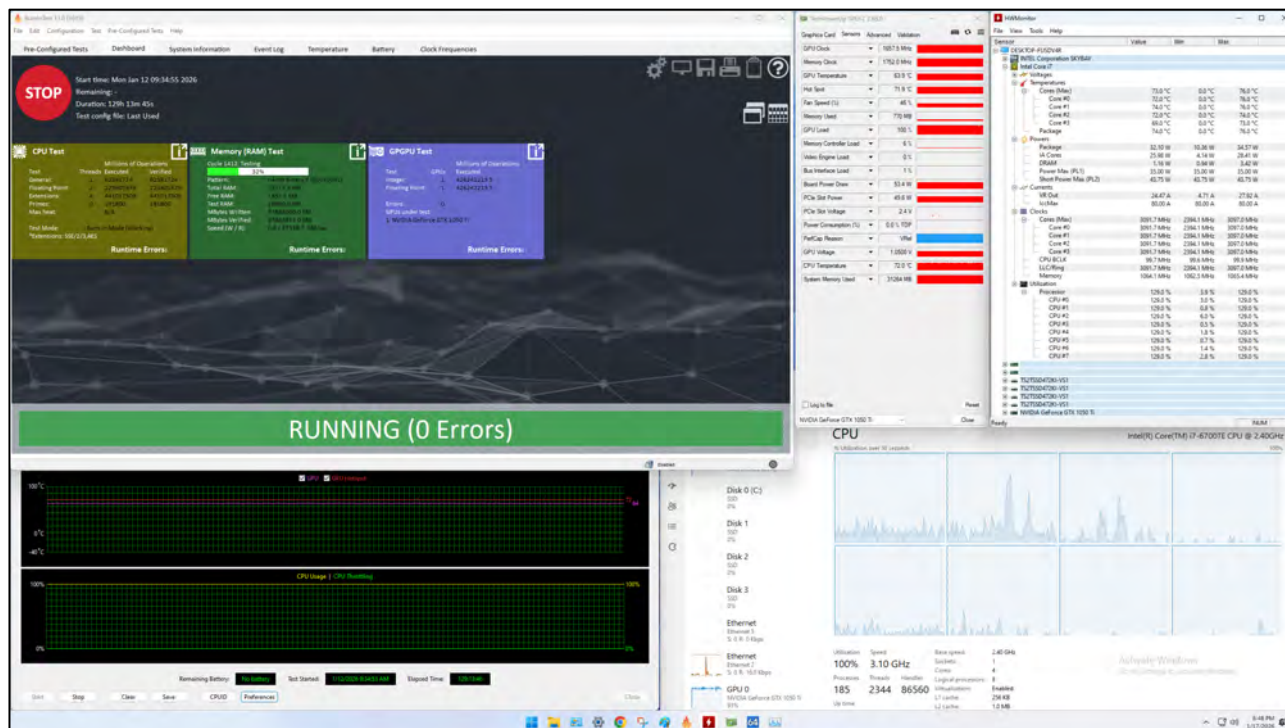




# PERFORMANCE TEST REPORT

## HORUS420-R1

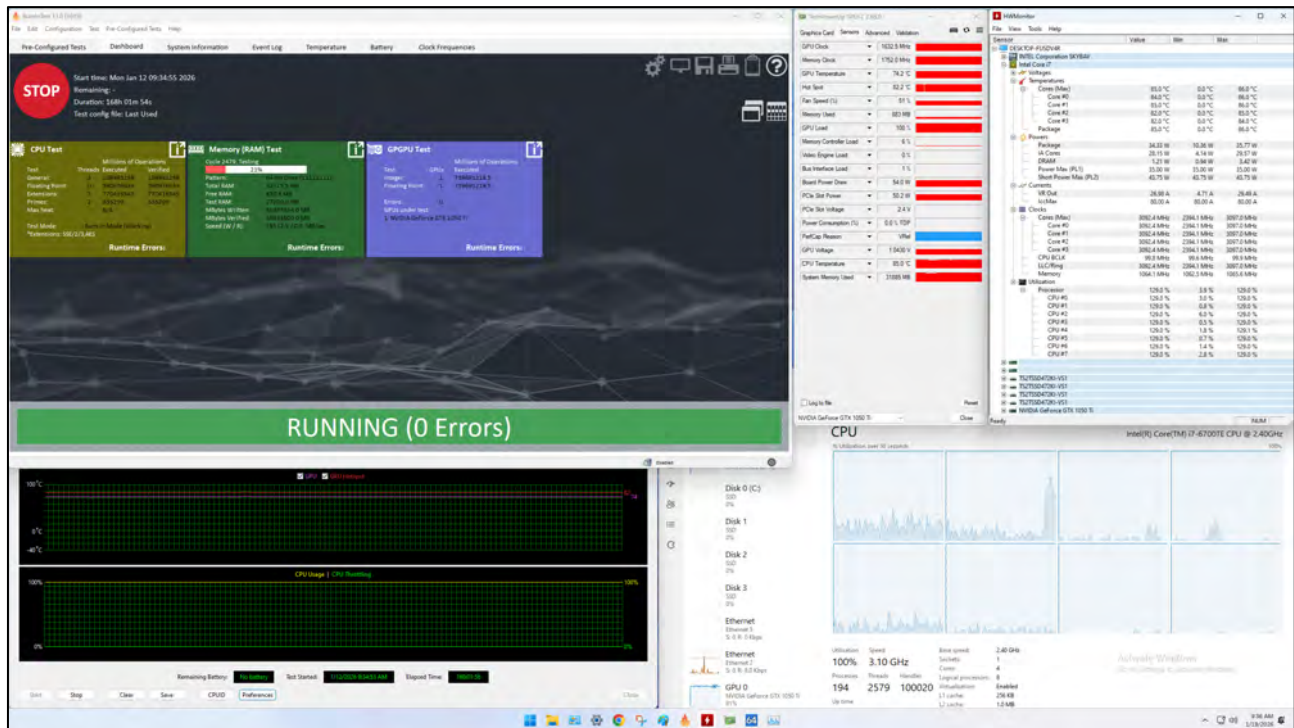
- Chamber in 40°C / 60%RH



# PERFORMANCE TEST REPORT

## HORUS420-R1

- Chamber in 50°C / 60%RH

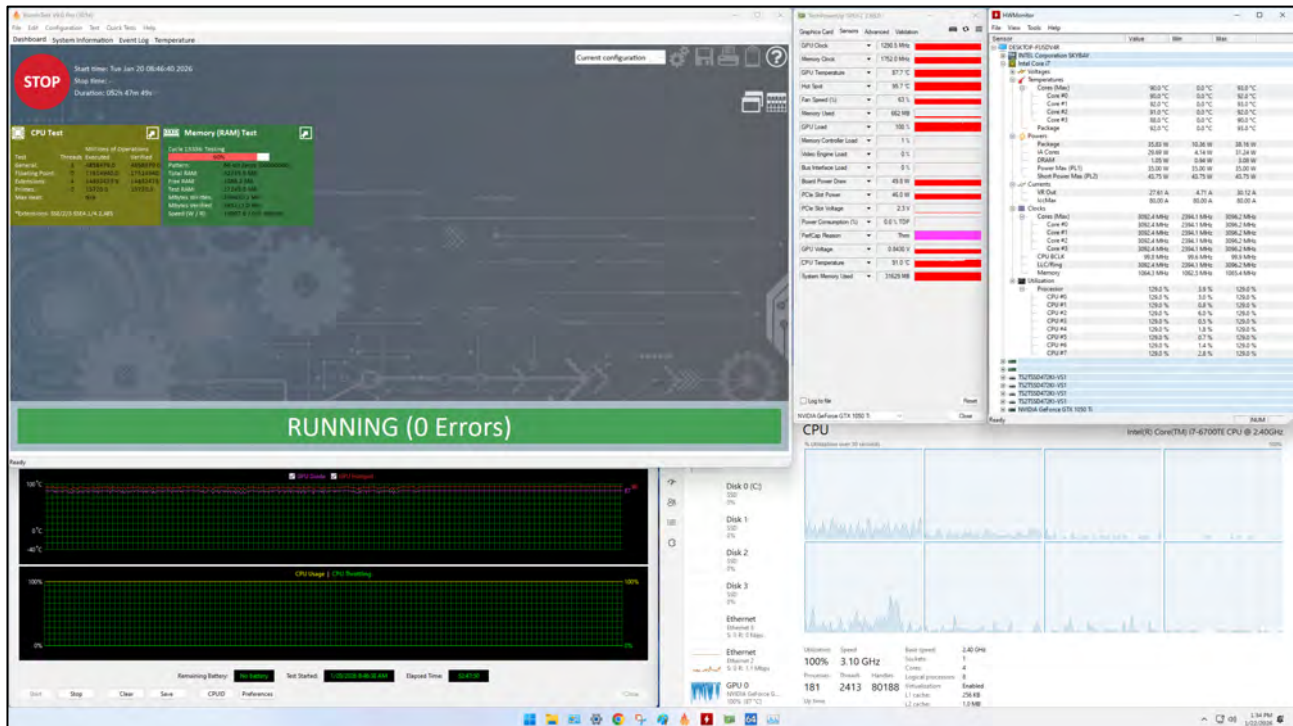




# PERFORMANCE TEST REPORT

## HORUS420-R1

- Chamber in 60°C / 60%RH





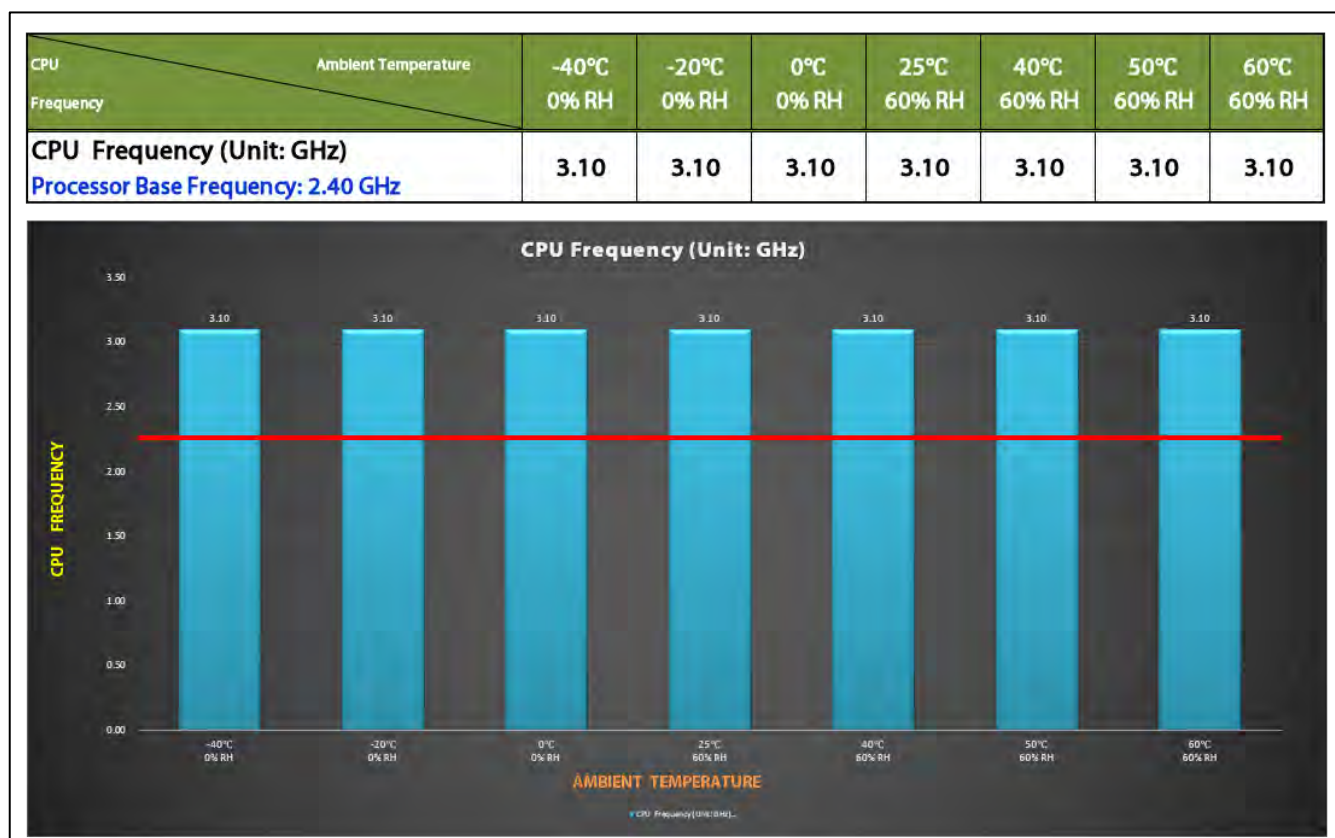
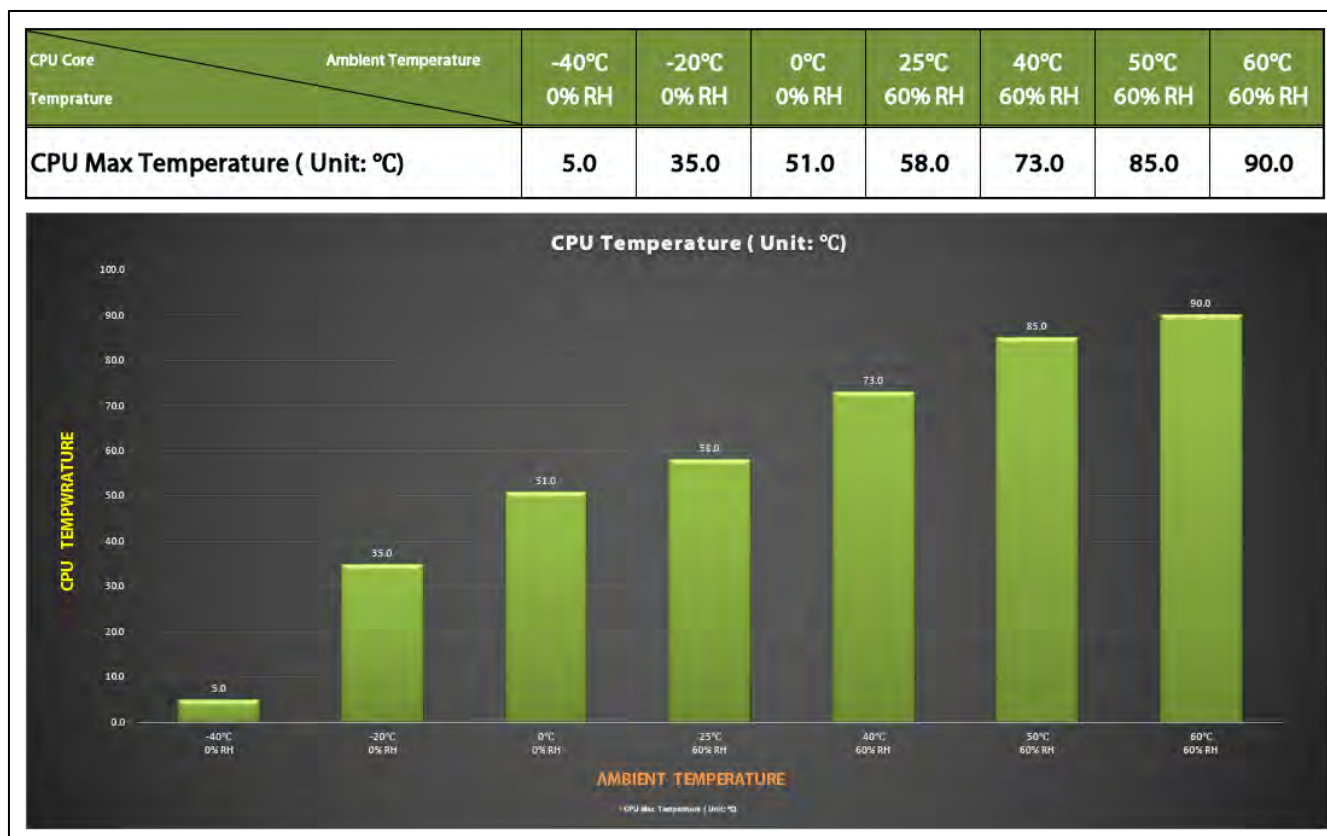
## 4. THERMAL TEST RESULT(-40°C ~ +60°C)

CPU & GPU Temperature and Frequency

| Temperature<br>Frequency             | Ambient Temp. | -40°C<br>0% RH | -20°C<br>0% RH | 0°C<br>0% RH | 25°C<br>60% RH | 40°C<br>60% RH | 50°C<br>60% RH | 60°C<br>60% RH |
|--------------------------------------|---------------|----------------|----------------|--------------|----------------|----------------|----------------|----------------|
| CPU Max Temperature ( Unit: °C)      |               | 5.0            | 35.0           | 51.0         | 58.0           | 73.0           | 85.0           | 90.0           |
| CPU Frequency (Unit: GHz)            |               | 3.10           | 3.10           | 3.10         | 3.10           | 3.10           | 3.10           | 3.10           |
| GPU Temperature ( Unit: °C)          |               | 16.3           | 19.3           | 22.7         | 47.5           | 63.9           | 74.2           | 87.7           |
| GPU Hot Spot Temperature ( Unit: °C) |               | 24.3           | 27.3           | 30.7         | 55.5           | 71.9           | 82.2           | 95.7           |
| GPU Frequency (Unit: MHz)            |               | 1708.5         | 1695.5         | 1695.5       | 1670.5         | 1657.5         | 1632.5         | 1290.5         |

# PERFORMANCE TEST REPORT

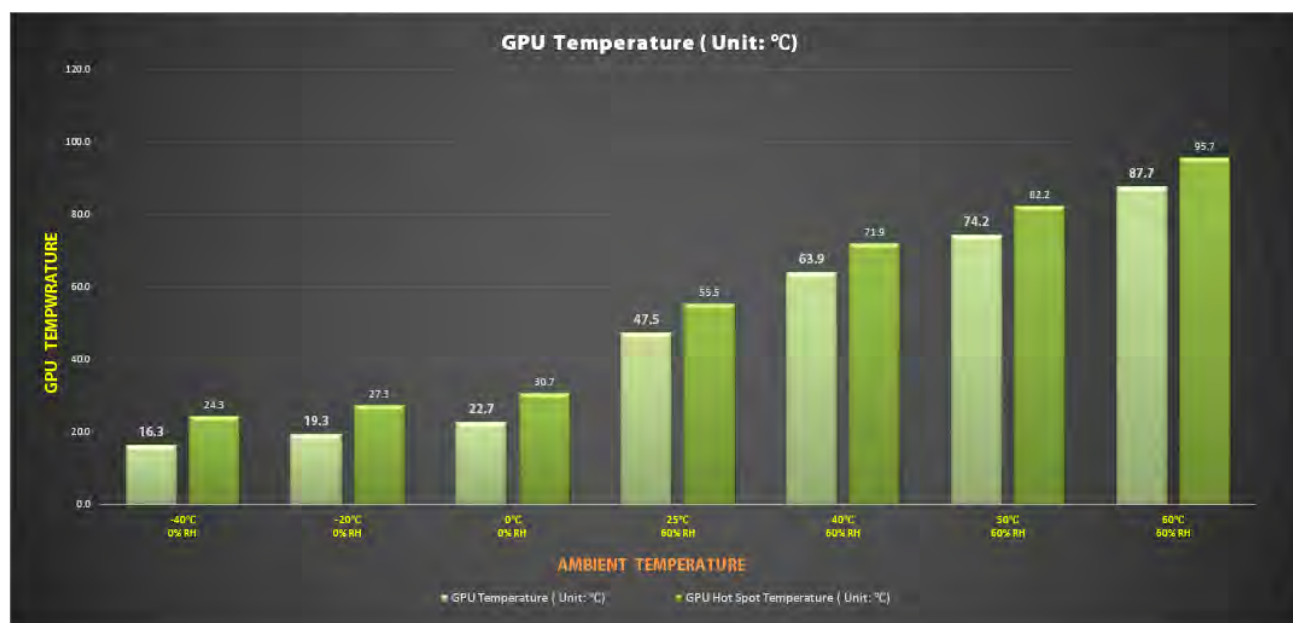
## HORUS420-R1



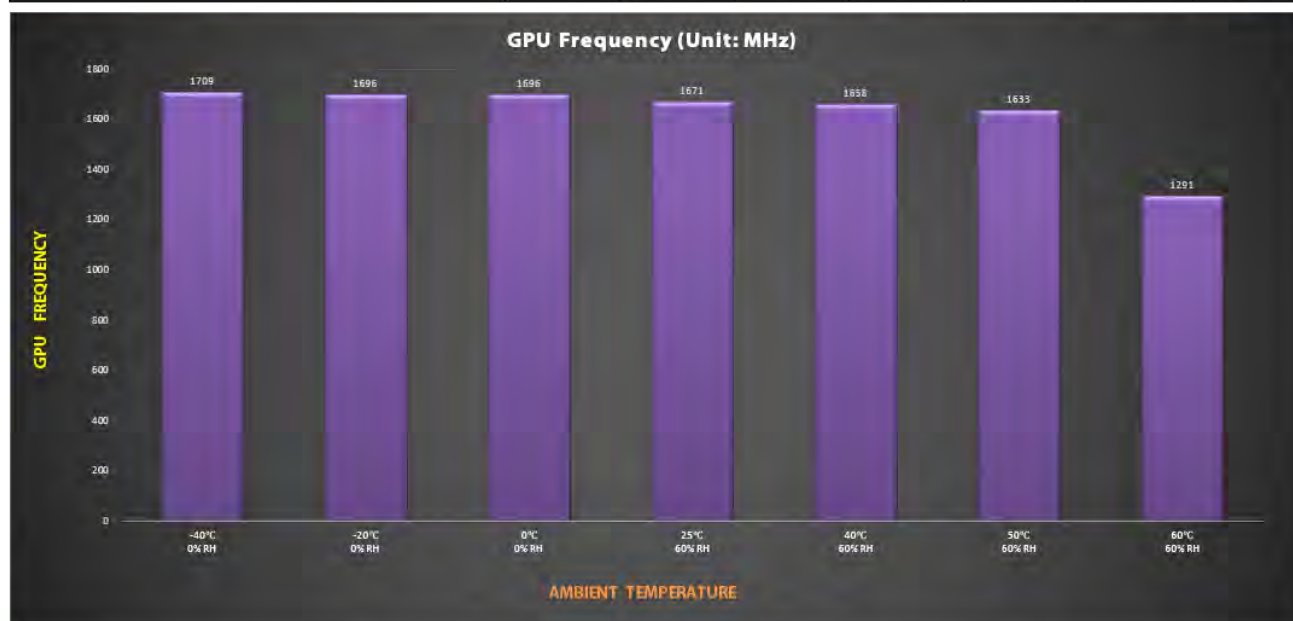
# PERFORMANCE TEST REPORT

## HORUS420-R1

| GPU<br>Temperature                   | Ambient Temperature | -40°C<br>0% RH | -20°C<br>0% RH | 0°C<br>0% RH | 25°C<br>60% RH | 40°C<br>60% RH | 50°C<br>60% RH | 60°C<br>60% RH |
|--------------------------------------|---------------------|----------------|----------------|--------------|----------------|----------------|----------------|----------------|
| GPU Temperature ( Unit: °C)          |                     | 16.3           | 19.3           | 22.7         | 47.5           | 63.9           | 74.2           | 87.7           |
| GPU Hot Spot Temperature ( Unit: °C) |                     | 24.3           | 27.3           | 30.7         | 55.5           | 71.9           | 82.2           | 95.7           |



| GPU<br>Frequency          | Ambient Temperature | -40°C<br>0% RH | -20°C<br>0% RH | 0°C<br>0% RH | 25°C<br>60% RH | 40°C<br>60% RH | 50°C<br>60% RH | 60°C<br>60% RH |
|---------------------------|---------------------|----------------|----------------|--------------|----------------|----------------|----------------|----------------|
| GPU Frequency (Unit: MHz) |                     | 1709           | 1696           | 1696         | 1671           | 1658           | 1633           | 1291           |





## 5. I/O FUNCTION TEST

### 5-1. LAN PORT

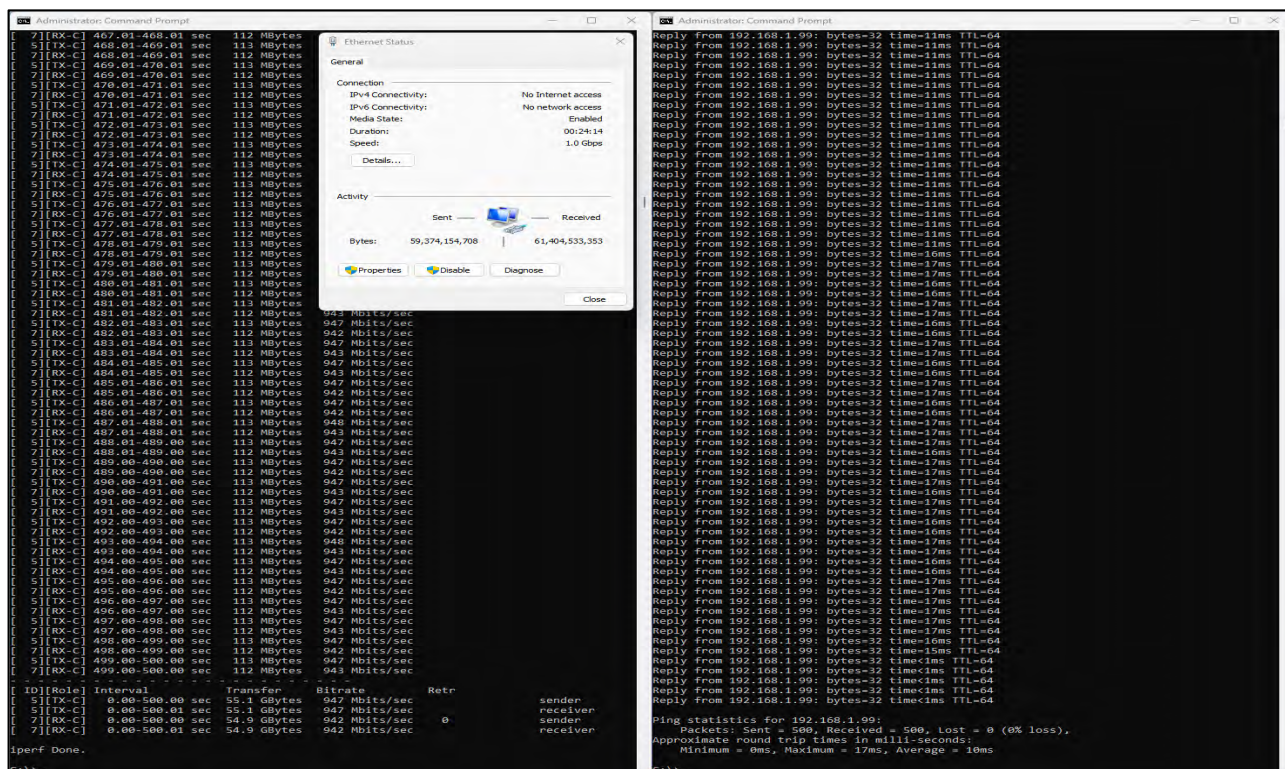


1GbE

LAN SPEED

LAN Data-Packet

LAN 1



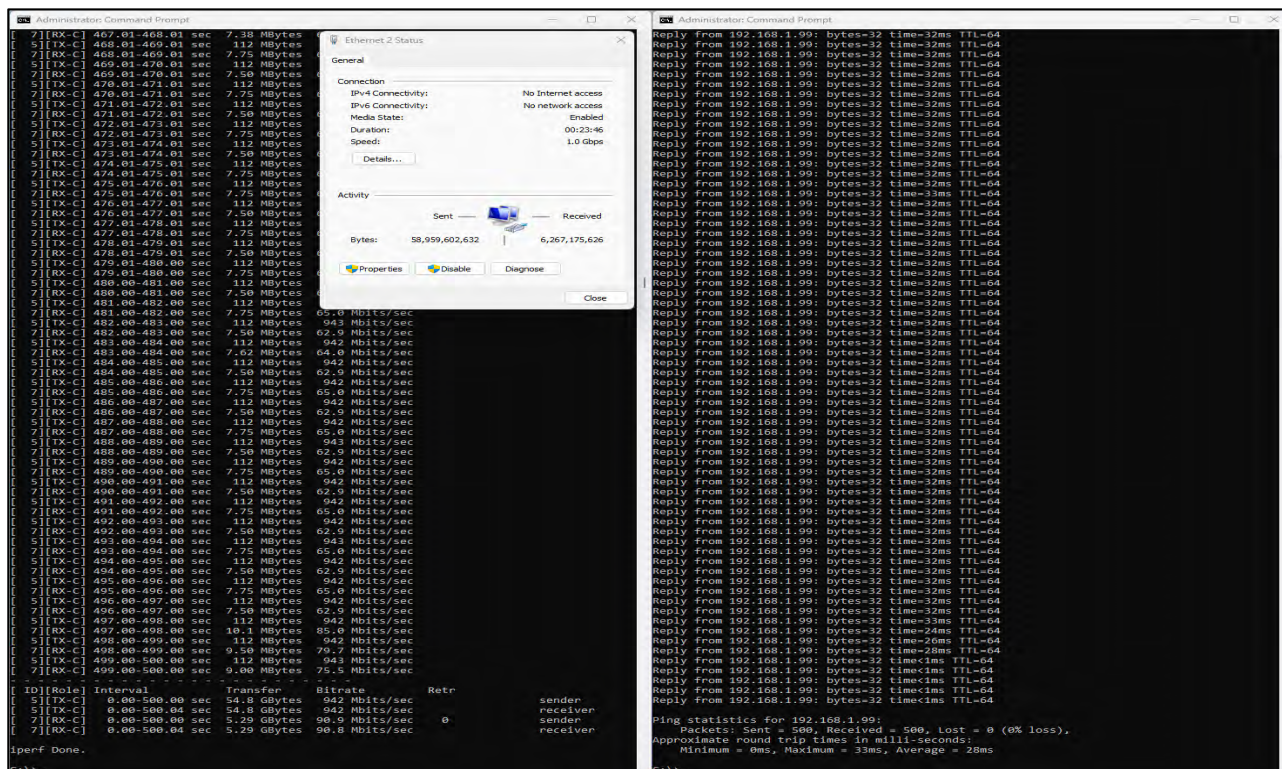
# PERFORMANCE TEST REPORT

## HORUS420-R1

LAN SPEED

LAN Data-Packet

LAN 2



LAN Speed Test Result: Pass

LAN Data-Packet Test Result: 0 Lost (0% loss)



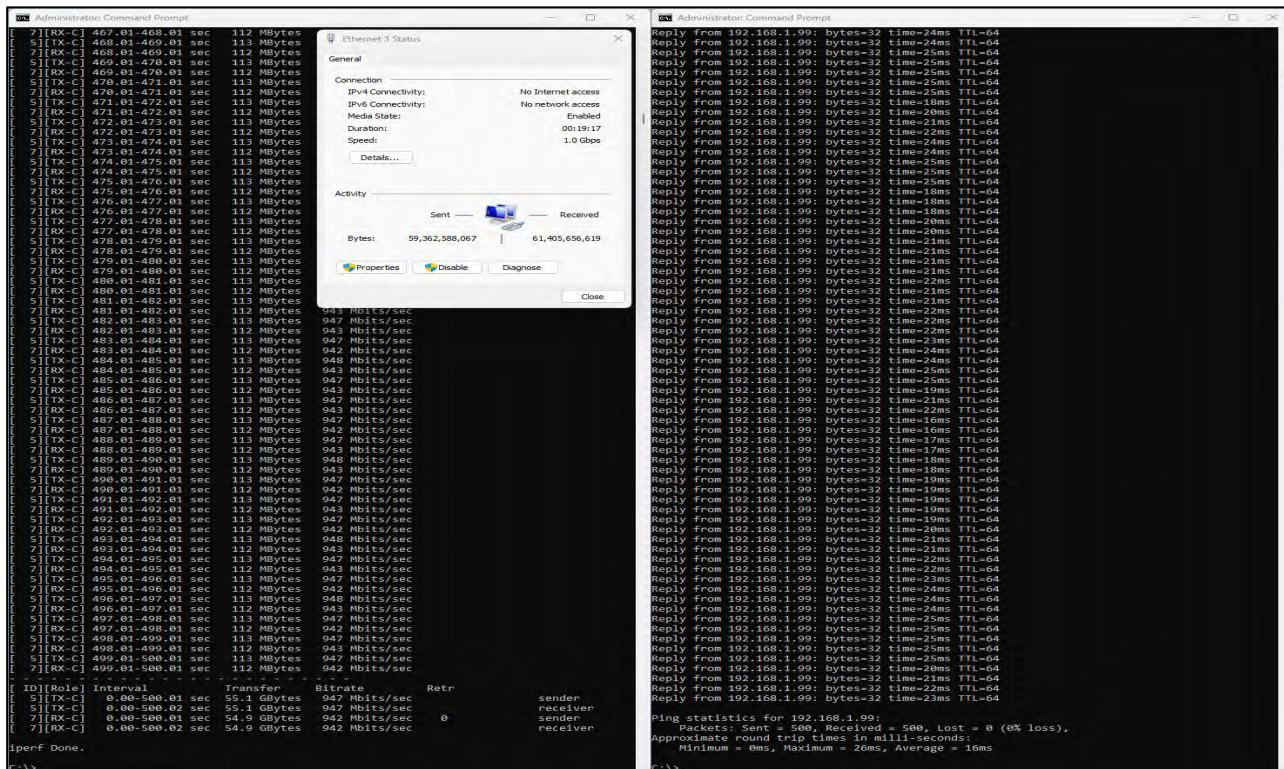
# PERFORMANCE TEST REPORT

## HORUS420-R1

LAN SPEED

LAN Data-Packet

LAN 3



LAN Speed Test Result: Pass  
LAN Data-Packet Test Result: 0 Lost (0% loss)



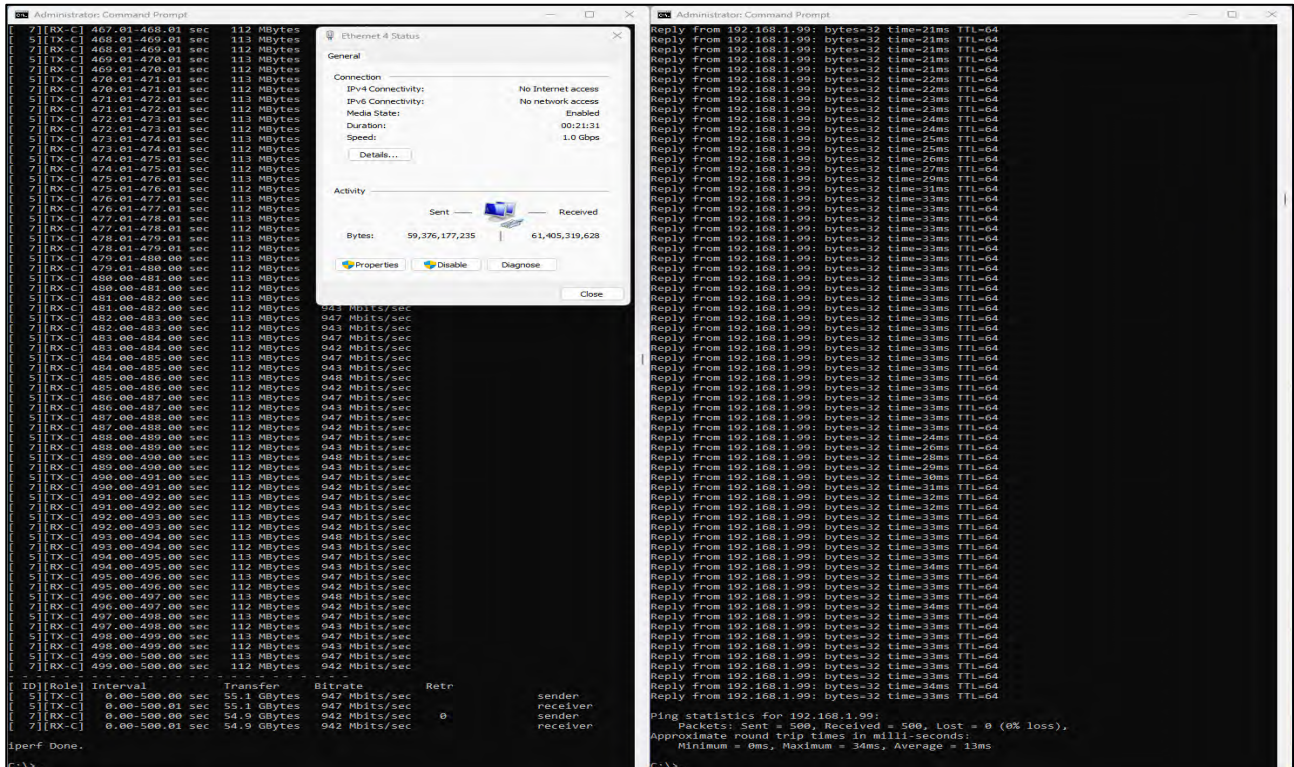
# PERFORMANCE TEST REPORT

## HORUS420-R1

### LAN SPEED

### LAN Data-Packet

LAN 4

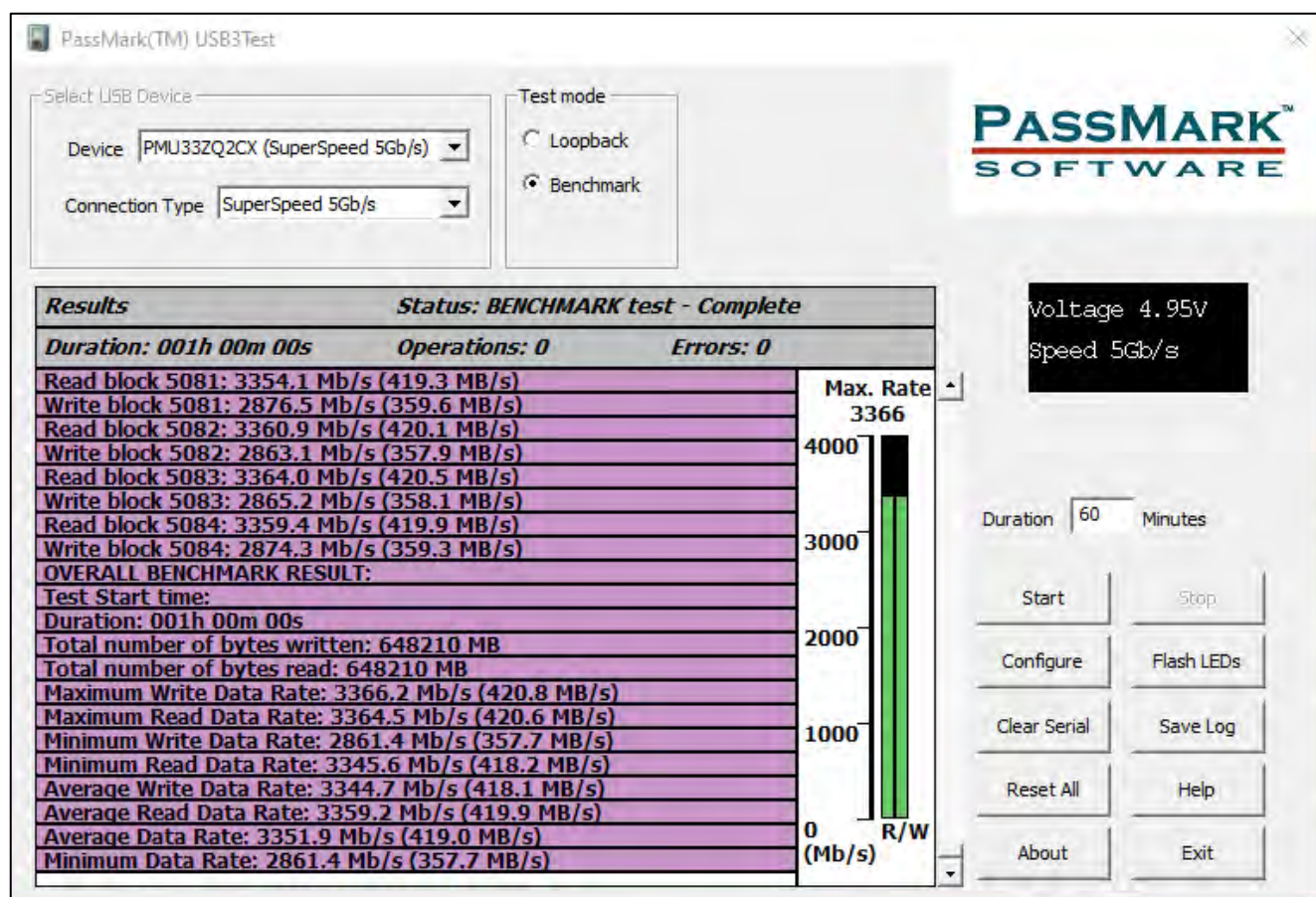


**LAN Speed Test Result: Pass**  
**LAN Data-Packet Test Result: 0 Lost (0% loss)**

## 5-2. USB PORT(REAR)



USB 3.0





# PERFORMANCE TEST REPORT

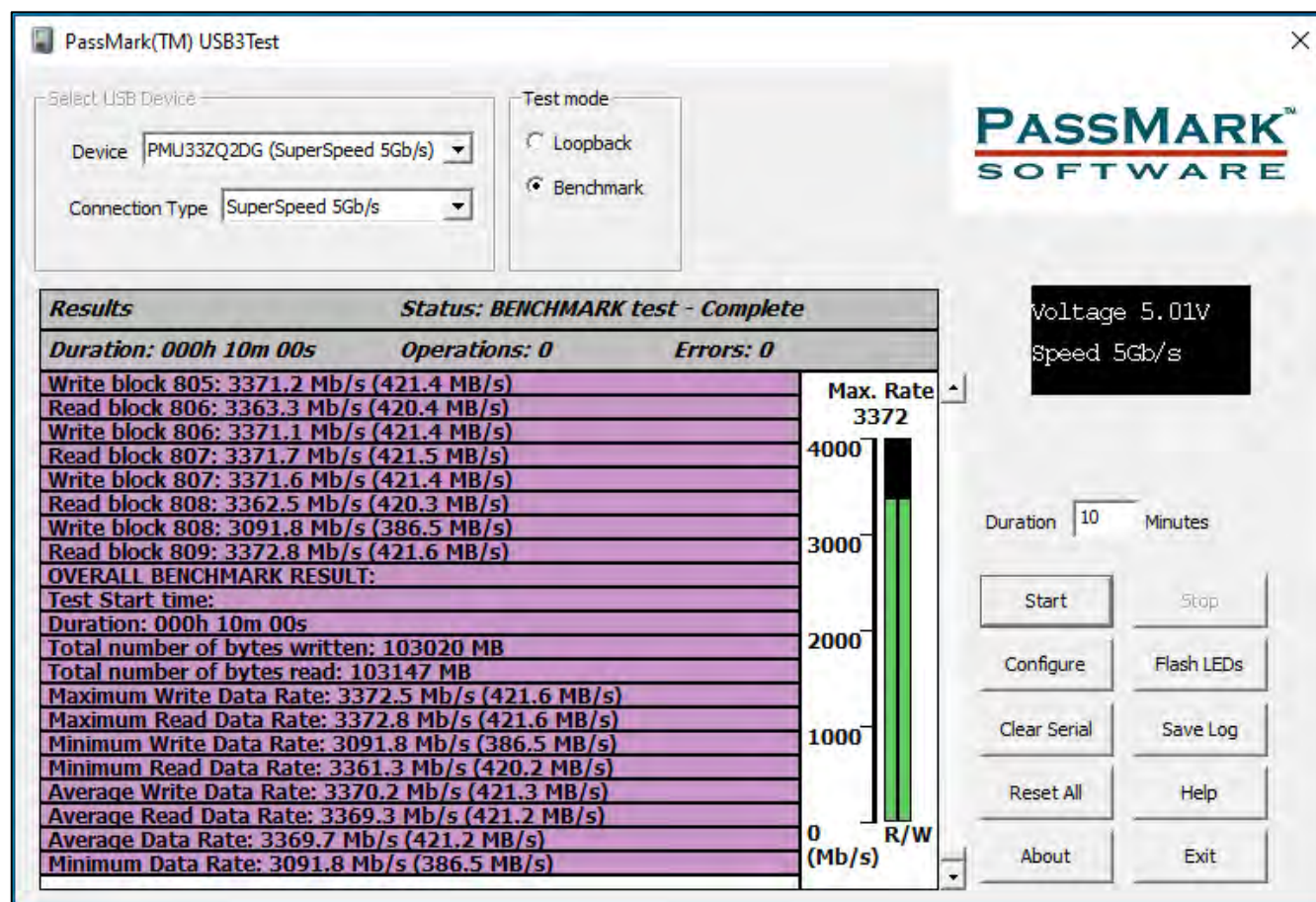
## HORUS420-R1





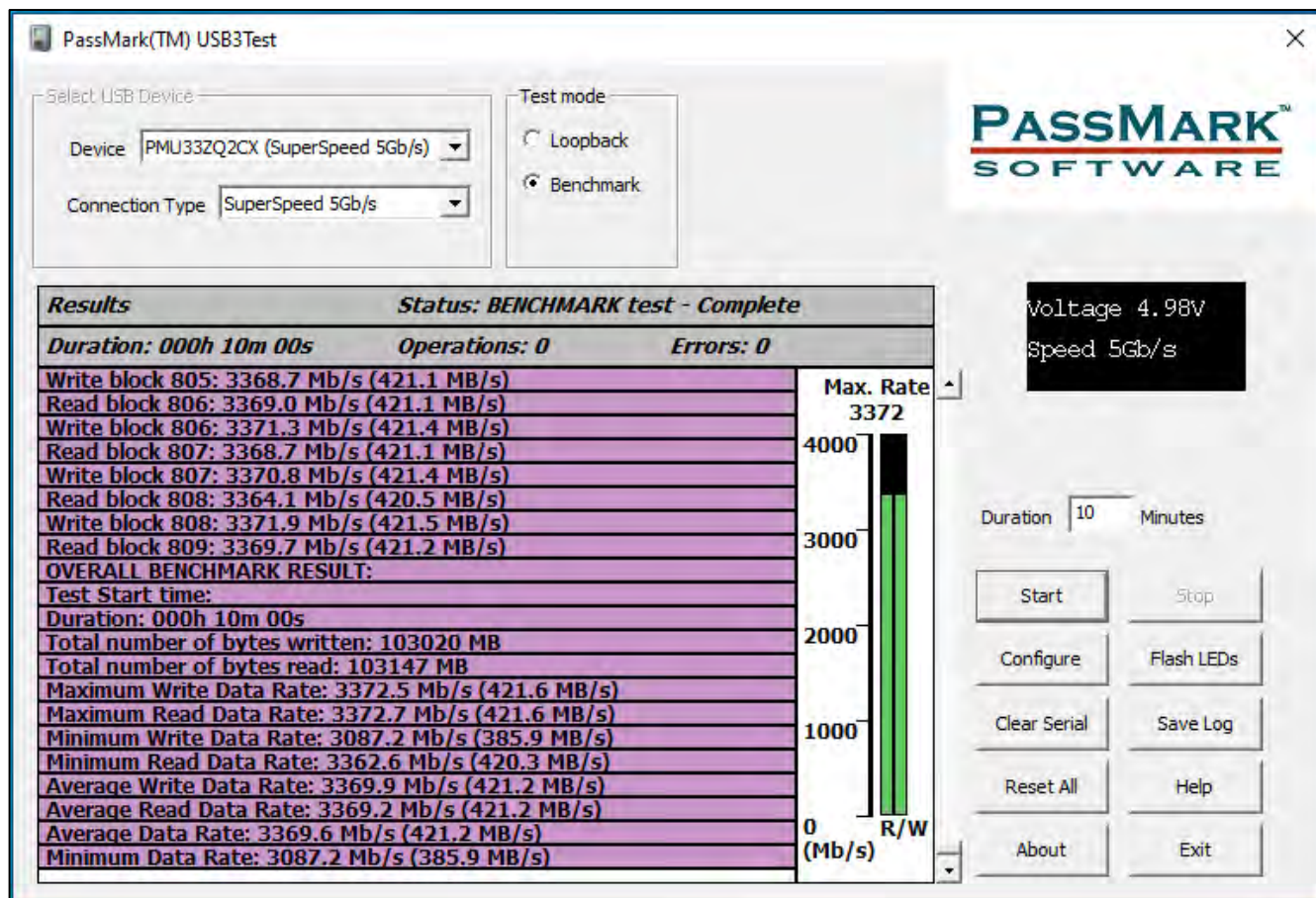
# PERFORMANCE TEST REPORT

## HORUS420-R1



# PERFORMANCE TEST REPORT

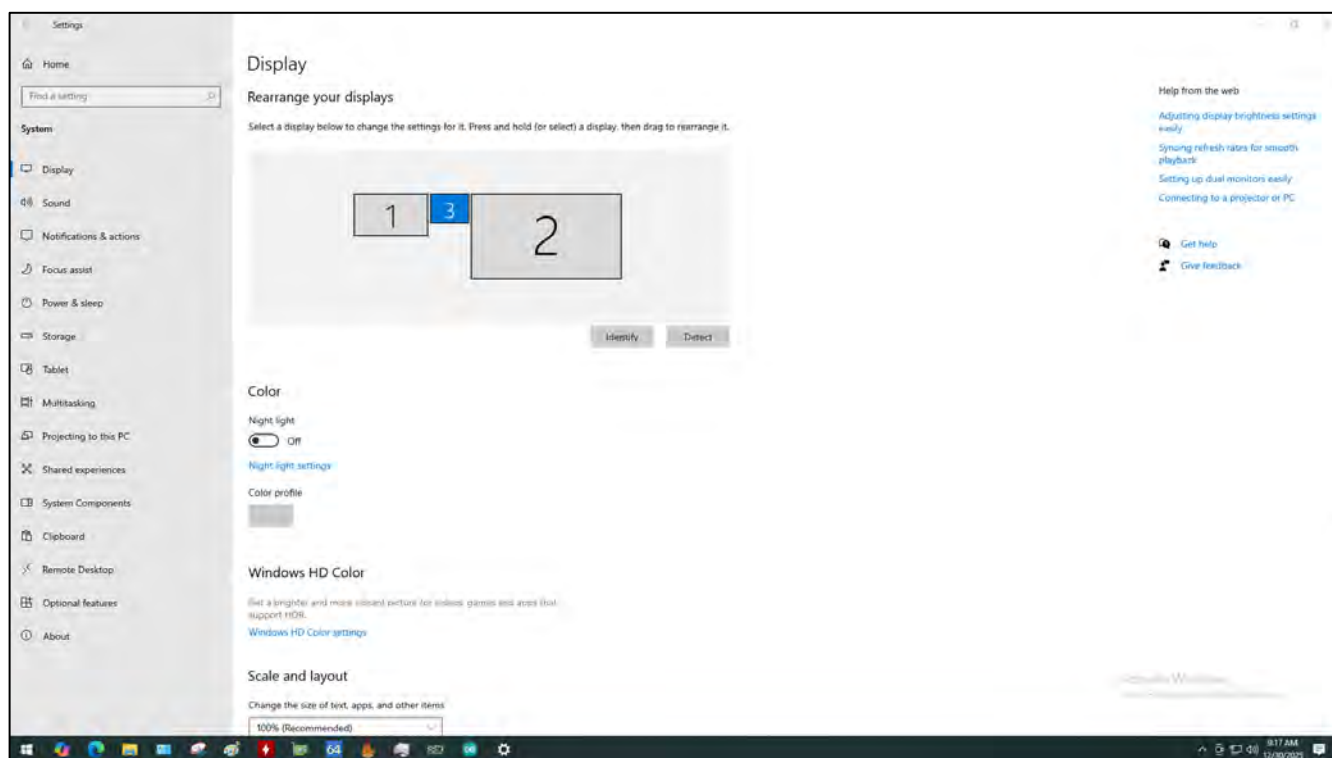
## HORUS420-R1



### 5-3. DISPLAY PORT



DP

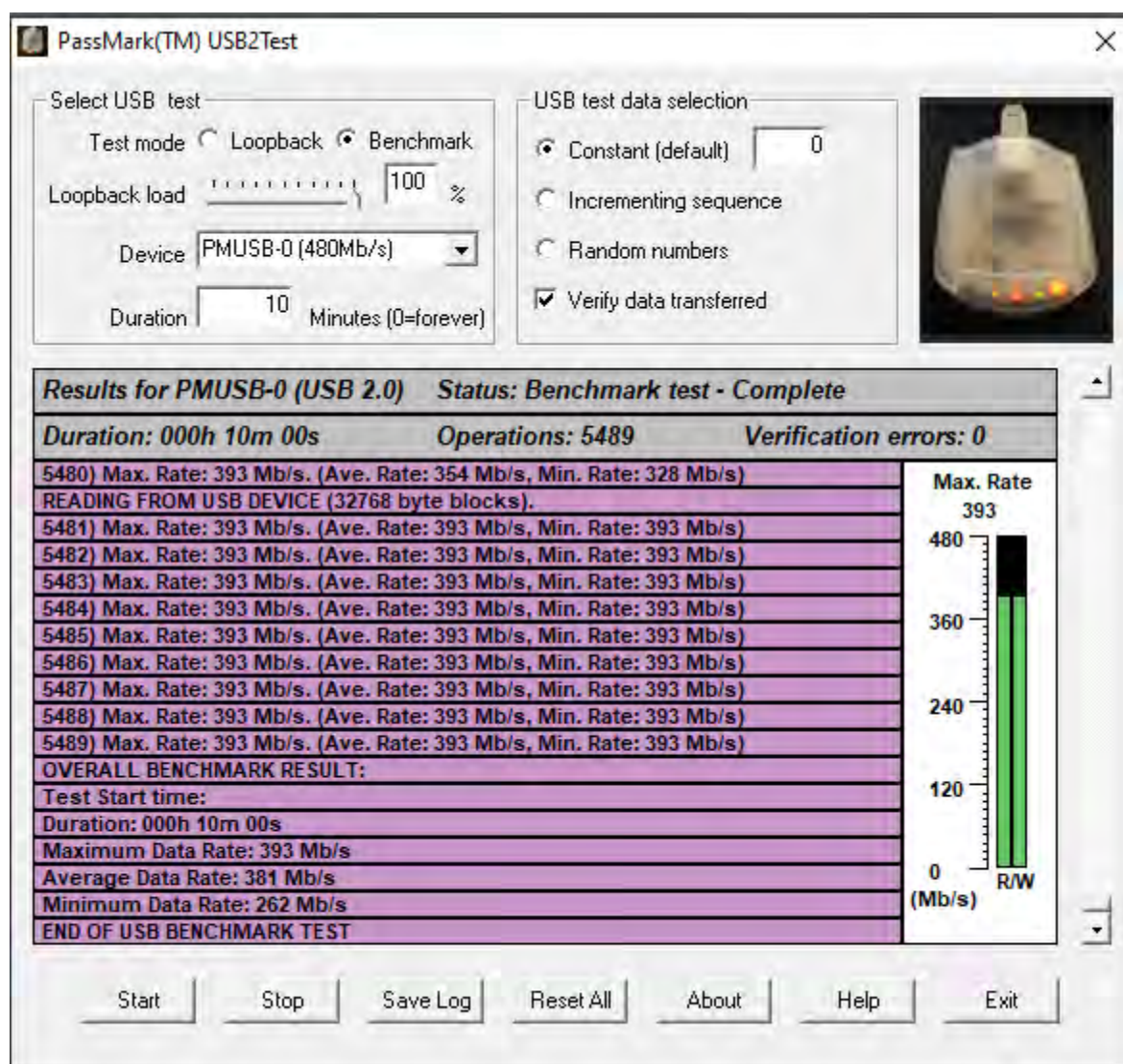




## 5-4. USB PORT (FRONT)

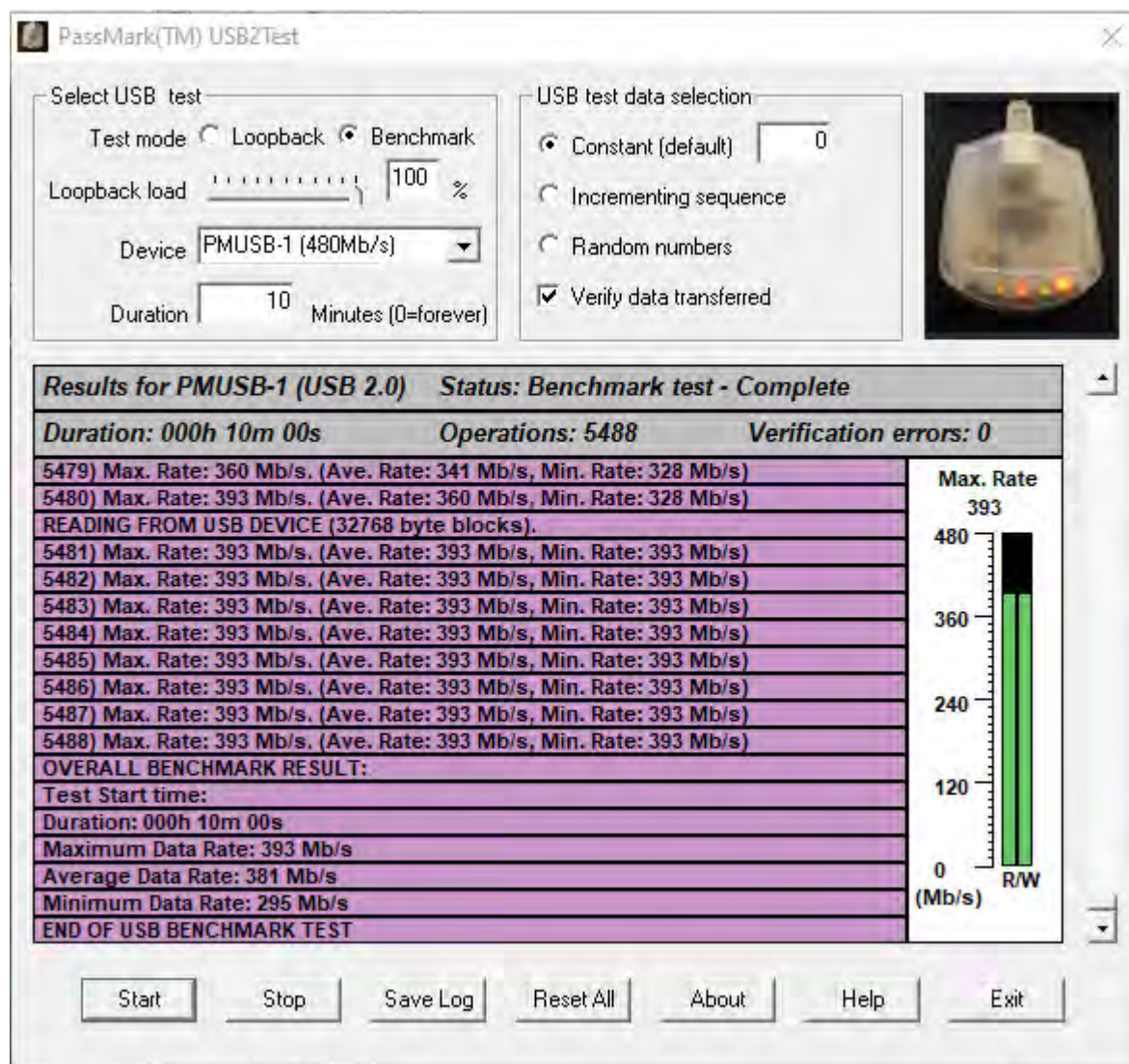


USB 2.0



# PERFORMANCE TEST REPORT

## HORUS420-R1



-----END-----